Universität Augsburg Mathematisch-Naturwissenschaftliche Fakultät Institut für Physik

Modulhandbuch

für den Masterstudiengang

Advanced Functional Materials (AFM)

Stand: 09.01.2012

Content

I. Goals and Profile of the AFM Masters program	2
II. Official documents	3
III. Module summary	4
IV. Module syllabi	
Module area 1 : Introduction to Materials Science	5
Module area 2 : Methods in Materials Science	11
Module area 3 : Materials Science Seminar	28
Module area 4 : Specialization in Materials Science	34
Module area 5 : Finals, Thesis	46

I. Objectives and Profile of the Program

This international Master of Science (MSc) aims at providing high-level academic and research-oriented education about the synthesis, the characterisation and the processing of all classes of materials with special emphasis on hybrids and ceramics.

The first objective is to promote excellence, innovation, originality, mobility, diversity as well as complementarity between European universities in the domain of functionalised advanced materials. Such a level of scientific education is unique in Europe.

The second objective is to bring highly-motivated third-country graduate students to Europe to allow them benefiting from an education in the technological domain of nanomaterials and materials science.

The final goal is to prepare the students for entering a PhD program in Europe or abroad for instance in one of the FAME network laboratories. Alternatively, students should be able to fill leading positions in industry as scientists or engineers in materials science.

The Master Course ensures an intensive and innovative training for both non-European and European students. The program forms a new generation of students with multidisciplinary and transdisciplinary profile and fosters networking activities within Europe and third countries in the field of research and education.

The 7 institutional partners offer a larger variety of knowledge as well as a broader spectrum on research than a single university could propose. The students benefit from the best practices used in work teams and take part to the management of scientific research-oriented projects. After having passed the first year in one partner university (currently either Univ. Augsburg or INP-Grenoble) the students are obliged to continue in one of the other partner universities in another country. Depending on the rules of the receiving university, they can do the master thesis under supervision of the first or second year university.

They have the opportunity to specialise in 7 different research areas:

- * Hybrid Materials and Ceramics
- * Materials for Micro- and Nanotechnologies
- * Nanomaterials and Hybrids
- * Engineering of Materials and Nanostructures
- * Nanomaterials and Modelling
- * Functional Ceramics
- * Materials Interfaces

The Augsburg Institute of Physics comprises one of the largest groups in solid state physics in Germany. The different chairs are not only known for their high- quality basic research but also for their application-oriented research and development activities. The excellence in basic research as a main pillar of the physics department is reflected for example by participation in several collaborative research centres, covering special topics of fundamental or applied solid state physics and modern materials. Additionally there is a growing cooperation with applied research centers for lightweight construction and application for carbon fiber reinforced materials.

Based on a detailed knowledge of advanced physical and chemical analysis, thin film technology, hard coatings, catalysis, nanoscience, surface science, oxide materials and life cycle analysis, there is - via the centre for Materials- and Environmental Research (AMU) - a close collaboration with industrial and institutional laboratories on a wide variety of topics. Europe-wide, the team of 15 partner organisations of EMMI institute supporting the FAME Master is focusing on smart nano-materials, an emerging field drawing inspiration from nature and the living world.

The FAME Masters program comprises five different module areas as listed below. Credit points (CP) and semester work load (SWS, given in hours per week for one semester) is given in the table, as well.

Module		SWS	CP
1	Fundamentals of Materials Science	15	23
2	Methods in Materials Science	23	33
3	Materials Science Seminar	2	4
4	Specialization in Materials Science	20	30
5	Finals		30

The total of credentials is 120 credit points.

The anticipated learning outcomes in the Masters program go far beyond the ones of the Bachelor's degree program. The following technical and social knowledge, skills and competencies are essential for the professional qualification of the Masters Graduates:

• The graduates have sound working knowledge of scientific fundamentals of materials science, good knowledge of mathematics (in terms of its application to scientific problems), and practical skills in modern materials research. Based on this knowledge, they are able to identify relations between materials science and various economic issues.

• Generally, they are well prepared for demanding tasks, whose processing goes well beyond a schematic application of existing concepts only. They are moreover able to analyze and deliberately modify the tasks according to the respective needs. They have acquired a wide range of material knowledge, scientific methods and techniques and are qualified to use these accordingly and well adapted to the specific problem.

• The graduates have an understanding of the impact of their activities as material scientists in a company, including resource and environmental issues and are aware of their own scientific and social responsibilities.

• The graduates are able to judge and understand the effects of their actions as materials scientists and to estimate their impact on social, environmental and society issues. They have accquired an awareness for resource management and smart resource handling.

• The program graduates are able to work in a variety of scientific and technical surroundings to organize and carry out projects in several different areas. They are familiar with the learning strategies that lead them and others to professional and social competences and they know how to make this anongoing and deepening process.

• They are able to appropriately present both their own results as well as general questions of modern materials research in front of professional colleagues as well as to the broader public.

• They are prepared for flexible use in various professional fields around and in particular on the work in an occupational or academic field. Successful graduates are well prepared to follow an appropriate PhD program.

Social skills are acquired primarily integrated into the specialized modules, such as team skills in exercises and in internships and project organization during the final thesis work. The Master's degree Materials Science is an international program, the teaching language of the courses is English.

II. Official Documents

The international Masters program, Materials Science' was officially opened to students in the winter term 2003/04. The actual examination regulation was enacted on 25. July 2007. It may be downloaded at

http://www.zv.uni-augsburg.de/de/sammlung/download/

or

http://www.physik.uni-augsburg.de/studium/

III. Module summary

The responsible module appointees are named in brackets.

Abbreviations:

SWS = Semester work load, CP = credit points V = lecture, \ddot{U} = exercise, P = Prakticum, S = Seminar

Module Group	Module	Signature	SWS	СР
1		-		
Basics of Mate-	Compulsory Modules:			
rials Science	Materials Physics I (Stritzker)	MaMawi-11-01	3 V, 1 Ü	6
	Materials Physics II (Stritzker)	MaMawi-12-01	3 V, 1 Ü	6
	Materials Chemistry (Volkmer)	MaMawi-13-01	3 V, 1 Ü	6
	Physics of Surfaces and Interfaces (Horn)	MaMawi-14-01	3 V, 1 Ü	5
		subtotal	16	23
2				
Methods in Materials Science	Compulsory Modules: Characterization of materials (Haider)	MaMawi-21-01	4 V	6
	Processing of materials (Haider)	MaMawi-22-01	3 V	5
	Theoretical Concepts and Simulation (Schuster)	MaMawi-23-01	3 V, 1 Ü	6
	Elective Modules:			
	Method Course: Electron Microscopy (Haider)	MaMawi-24-02	4 V, 2 P	8
	Method Course: Electronics for Physicists and Materials Scientists (Wixforth)	MaMawi-24-04	3 V, 3 P	8
	Method Course: Materials Synthesis (Scherer)	MaMawi-24-05	2 V, 4 P	8
	Method Course: Methods in Biophysics (Thalhammer)	MaMawi-24-06	4 V, 1 P	8
	Method Course: Optical Properties of Solids (Loidl)	MaMawi-24-07	2 V, 4 P	8
	Method Course: Spectroscopy on Con- densed Matter (Loidl)	MaMawi-24-09	2 V, 4 P	8
	Method Course: Thin Film Analysis with Ion Beams (Karl)	MaMawi-24-11	2 V, 4 P	8
	Method Course: X-ray and Neutron Dif- fraction Techniques (mit Exkursion) (Scherer)	MaMawi-24-12	2 V, 4 P	8
	Method Course: Solid State Synthesis Lab (Volkmer)	MaMawi-24-13	2 V, 4 P	8
	Method Course: Semiconductor and sur- face acoustic wave devices (Krener)	MaMawi-24-14	4 V, 1 P	8
	Method Course: Characterization of Por- ous Materials (Volkmer)	MaMawi-24-15	2 V, 4 P	8
		subtotal	22	33
3				
Materials Scien- ce Seminar	Compulsory Module: Introduction to Materials (Haider)	MaMawi-31-01	2 S	4

subtotal	2	4
Subtotal	2	-

4				
Specialization in Materials Scien-	5 Elective Courses according to postings of examination board			
се				
	Physics and Technology of Semiconduc-	MaMawi-41-01	3 V, 1 Ü	6
	tor Devices (Wixforth)			
	Nanostructures / Nanophysics (Wixforth)	MaMawi-41-02	<u>3 V, 1 Ü</u> 3 V, 1 P	6
	Electronics for Physicists and Materials Scientists (Wixforth)	MaMawi-41-03	3 V, 1 P	6
	Biophysics and Biomaterials (Thalham- mer)	MaMawi-41-04	4	6
	Solid State Spectroscopy with Synchro- tron Radiation (Kuntscher)	MaMawi-41-05	3 V, 1 Ü	6
	Chemische Physik I (Scherer)	MaMawi-41-06	3 V, 1 Ü	6
	Chemische Physik II (Scherer)	MaMawi-41-07	3 V, 1 Ü	6
	Ion-Solid Interaction (Karl)	MaMawi-41-08	3 V, 1 Ü	6
	Physics of Thin Films (Brütting)	MaMawi-41-09	4 V	6
	Organic Semiconductors (Brütting)	MaMawi-41-10	4 V	6
	Magnetism (Krug von Nidda)	MaMawi-41-11	3 V, 1 Ü	6
	Low Temperature Physics (Mannhart)	MaMawi-41-12	3 V, 1 Ü	6
	Spintronics (Mannhart)	MaMawi-41-13	4 V	6
	Materials Synthesis (Scherer)	MaMawi-41-14	3 V, 1 Ü	6
	Oxidation and Corrosion (Haider)	MaMawi-41-15	4 V, 1 Ü	6
	Seminar on Glass Physics (Lunken- heimer)	MaMawi-41-16	2 S	4
	Advanced Solid State Materials (Höppe)	MaMawi-41-17	3 V, 1 Ü	6
	Porous Materials (Volkmer)	MaMawi-41-18	3 V, 1 Ü	6
	Superconductivity (Tidecks)	MaMawi-41,19	3 V, 1 Ü	6
	Sustainable Resource Management (Rathgeber, Reller)	MaMawi-41-20	2 V, 2 Ü	6
	Practical Laboratory Project (Chairman of Examination Board)	MaMawi-42-01	4 V	6
5			•	
Finals	Masters Thesis (6 months) (Wixforth)	MaMawi-91-01		26
	Final Colloquium (Wixforth)	MaMawi-91-02		4
		subtotal	1	30
		Total		120

IV. Module descriptions

1. Basics of Materials Science

Modul description	Material Physics I							
Signature	MaMawi-11-01, MaAFM-11-01							
Semester and recurren-	1 st Semester/ every winter term							
Responsible for module	Prof. Dr. Stritzker							
Lecturer								
Language	Englisch							
Curriculum inclosures	Master Materials Science, Master Advanced Functional Materials							
	Туре	SWS		Gro	up size			
Lecture type and hours	Lecture							
	Exercise	1		20				
		Presence tim		'y	Total			
Work load	Lecture	45	55		100			
(hours)	Exercise	15	35		50			
(written examen		30		30			
A					180			
Credit points	6							
Prerequisites acc.to the regulations of study	None							
Recommended prerequi-								
sites	None							
Acquired skills and knowledge	 The students know the basic terms of solid state and semi-conductor physics like electrical band structure, doping, charge carrier stastics or optical properties. are capable to apply derived approximations as the effective mass or quasi Fermi-levels to describe the basic characteristics of semi-conductive materials. have the competence to apply these concepts for the description of semiconducting components as diodes, transistors and optical components and to describe their functionality. know the most important technological procedures for manufacturing of micro- and nanoelectronic components. 							
Content	 IA Preliminaries IB Electrons in solids IB 1 Free Electron Gas IB 2 Reciprocal Lattice IB 3 Band Structure IC Phonons IC 1 Lattice Vibrations ID General Properties of Materials ID 1 Electrical Conductivity ID 2 Thermal Properties ID 3 Optical Properties II Metals III Metals III Semiconductors Pure SC Intrinsic Conditions SC in Equilibrium Doping 							

	 Heterogeneous Structures Metal-SC Interfaces, Schottky Contact pn-junctions Devices Diode Transistor Solar cell Technology IV Dielectric Solids, Optical Properties Introduction, Phenomenology Polarization Propagation of EM waves in Solids
	Ferro electricityOptically active point defects
Requirements for credits	One written exam, 90 min, and one seminar presentation (20 min)
Media and methods	Lecture: slides/blackboard with help of other media and experiments Tutorial: intensive support in small groups, seminar presentations by students Self-study
Literature	 R.E. Hummel: <i>Electronic Properties of Materials</i> Springer 2001 (UP1000 H925) G. Burns: <i>Solid State Physics</i> Academic Press 1990 (UP1000 B967) N. W. Ashcroft, N.D. Mermin: <i>Solid State Physics</i> (UP1000 A 824) C. Kittel: <i>Introduction to Solid State Physics</i> (UP1000 K 62)
Further Information	-

Module description	Materials Physics II								
Signature	MaMawi-12-01, MaAFM-12-01, MaPhy-42-02								
Semester and recur-	2 nd c	2 nd Semester / each summer term							
rence	S								
Responsible for module	Prof.	Dr. Stri	itzker						
Lecturer		Prof. Dr. Stritzker (SS 2011)							
Language		English							
			rialwisse	nschafte	n. Mast	er Advar	nced Fur	ctional Mate	rials. Master
Curriculum inclosures		Master Materialwissenschaften, Master Advanced Functional Materials, Master Physik (Wahl)							
	1 1193	iii (wai	Type		SWS		Group	sizo	
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Lecture type and nours			tutorial)	1		30-40		
	-		lutorial	Dress		Calf		Tatal	
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Work load		Lectu		45		55		100	
(hours)		Tutori		15		35		50	
(Home	ework			30		30	
								180	
Credit points	6								
Prerequisites acc. to									
the regulations of study	Non	Э							
Recommended prere-	1								
quisites	None	а							
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		lannier	Dereich	en weitge	enenu s	einstant	iig zu be	arbeiten.	
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		1.2. At	omic orig	in of mag	gnetic m	oments			
	1.3. Paramagnetism								
		1.4. Fe							
		1.4. Fe 1.5 Ar							
		1.5. Ar	nisotropy		vriale br	ard and a	soft mag	nots	
		1.5. Ar 1.6. Fe	nisotropy erromagn	etic mate	erials, ha	ard and s	soft mag	nets	
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	 5. Atomic transport [3] 5.1. Diffusion 5.2. Electro-, thermo-, stress migration
Requirements for cre- dits	1 written examination, 90 min
Media and methods	Beamer presentation, blackboard (occasionally)
Literature	 Charles Kittel: Introduction to Solid State Physics (Wiley & Sons) Werner Buckel und Reinhold Kleiner: Supraleitung (Wiley-VCH)
Further information	-

Module description	Materials Chemistry							
Signature		Madenais Chemistry MaMawi-13-01, MaAFM-13-01, MaPhy-41-04, MaPhy-42-06						
Semester and recur-		1 st semester (each winter term)						
rence	1 · ` Se	emester (ead	cn winter te	m)				
Responsible for module		Prof. Dr. Volkmer						
Lecturer		Prof. Dr. Volkmer						
Language	englis							
Curriculum inclosures		Master Materials Science (compulsory module), Master Physics with minor sub- ect Chemistry (elective module), Master AFM (compulsory module)						
		type		SWS		Group	size	
Lecture type and hours			ures	3		20-30		
	 	tuto		1	T	20-30		
			Prese	nce	Self-s	tudy	Total	
	-	laaturaa	time 45		30		75	
Work load	-	lectures tutorial	45		60		75	_
(hours)		homework	15		30		30	
		nomework			30			
Cradit paints							180	
Credit points Prerequisites acc. to	6 LP							
the regulations of study	none							
Recommended prere-								
quisites	The le	ecture cours	e is based	on the co	urses C	hemistry	/ I and Chemi	stry II.
knowledge	• le	 stability and reactivity of coordination compounds learn how to transfer concepts of coordination chemistry onto topics of materials sciences 						
Content	• • • • •	 Historical development of coordination chemistry [1] Structures and nomenclature rules [2] Chemical bonds in transition metal coordination compounds [3] Stability of transition metal compounds [2] Characteristic reactions [4] Coordination polymers / metal-organic frameworks [2] Cluster compounds [2] Functional materials [2] Bioinorganic chemistry [2] Coordination compounds in medical applications [1] 						
Requirements for cre- dits	1 writ	ten examina	ation, 90 mi	ו				
Media and methods	Beam	er presenta	tion, blackb	oard (oco	casional	ly)		
Literature	• Lutz	 Beamer presentation, blackboard (occasionally) Coordination Chemistry, Joan Ribas Gispert, Wiley-VCH Lutz H. Gade, Koordinationschemie, Wiley-VCH As well as selected reviews and journal articles cited on the slides 						
Further information	-							
	1							

Module description	Physics of Surfaces and Interfaces							
Signature	MaMawi-14-01; MaAFM-14-01; MaPhy-42-03							
Semester and recur-	2 nd semester / every year							
rence								
Responsible for module	Prof.	Prof. Dr. Horn						
Lecturer			er (SS 2011)					
Language		englisch						
Curriculum inclosures			als Science; M	aster AFM; Mas	ter Physics (elect	tive module)		
			Туре	SWS	Group size	,		
Lecture type and hours			ectures	3	bis zu 40			
51			utorial	1	bis zu 20			
				Presence	Self-study	Total		
		lectures	6	45	45	90		
Work load		tutorial		15	45	60		
(hours)		homew	ork		30	30		
			-			180		
Credit points	5							
Prerequisites acc. to								
the regulations of study	none							
Recommended prere-	Das		nerimentelle F	estkörnernhveik	oder das Modul	Theoretische	Fest-	
quisites				solviert werden			. 001-	
Acquired skills and knowledge	 Die Studierenden haben Kenntnisse der Struktur, der elektronischen Eigenschaften, der Thermodynamik sowie des chemischen Reaktionsverhaltens an Ober- und Grenzflächen, haben die Fertigkeit, ihre Kenntnisse auf Problemstellungen der Grundlagenforschung und der angewandten Forschung auf dem Gebiet der Physik von Ober- und Grenzflächen anzuwenden, und besitzen die Kompetenz, basierend auf den vermittelten physikalischen Grundlagen eigenständig Lösungsansätze für entsprechende Problemstellungen zu erarbeiten. 							
Content	1 II. Sc 1 2 3 1II. Pl 1 2 3 4 5 6 7 1V. M exam	 Introduction [1] The importance of surfaces and interfaces Some basic facts from solid state physics [3] Crystal lattice and reciprocal lattice Elektronic structure of solids Lattice dynamics III. Physics at surfaces and interfaces [14] Structure of ideal and real surfaces Relaxation and reconstruction Transport (diffusion, elektronic) on interfaces Elektronic structure of surfaces Elektronic structure of surfaces Chemical reactions on solid state surfaces (catalysis) Interface dominated materials (nano scale materials) Methods to study chemical composition and electronic structure, application examples [4] Scanning electron microscopy Scanning tunneling and scanning force microscopy 						
Requirements for cre- dits			electron spectr nination, 90 mii					

Media and methods	-
Literature	 Ertl, Küppers: Low Energy Electrons and Surface Chemistry (VCH) Lüth: Surfaces and Interfaces of Solids (Springer) Zangwill: Physics at Surfaces (Cambridge) Feldmann, Mayer: Fundamentals of Surface and thin Film Analysis (North Holland) Henzler, Göpel: Oberflächenphysik des Festkörpers (Teubner) Briggs, Seah: Practical Surface Analysis I und II (Wiley)
Further information	

2. Methods in Materials Science

Module description	Charac	terization of	Materia	s				
Signature	MaMaw	MaMawi-21-01, MaAFM-21-01						
Semester and recur-	1 st or 2 ^t							
rence	1 013	1 st or 3 rd semester / each winter term						
Responsible for module	Prof. D	r. Haider						
Lecturer								
Language	english							
Curriculum inclosures	Master Materia	Materials Sci	ence (co	mpulso	ry modul	e); Mas	ter Advanced	d Functional
		Туре		SWS		Group	o size	
Lecture type and hours		lecture	S	4		30		
		tutorial		0		0		
			Preser	nce	Self-s	study	Total	
	lec	ctures	60		60		120	
Work load	tut	orial						
(hours)	ex	am			60		60	
							180	
Credit points	6							
Prerequisites acc. to the regulations of study	none							
Recommended prere- quisites	Grundk	enntnisse de	r Materia	wissen	schaften			
Acquired skills and knowledge	legende Die Stu • ken scha • verf • bes che	e Charakteris dierenden nen die grund aften, ügen über Ke itzen Kompet	ierungsm dlegender enntnisse enzen, di ktronische	ethoder n Chara der Ein ese Teo	n vorges akterisier nsatzmög chniken	tellt. ungsme glichkeite zur Unte	thoden der N en dieser Me ersuchung de	s 4 SWS grund- Materialwissen- ethoden, er strukturellen, enschaften von
Content	 X-ray diffraction [2] Mechanical characterisation [2] Optical methods [2] Elektrical mearsurements and characterisation [2] NMR spectroscopy [2] Spectroscopy using synchrotron radiation[2] Thermal analysis [2] Ion beam methods [2] Charakterisation of organic systems [2] Elektron microscopy [2] (Stand: Wintersemester 2009/2010) 							
Requirements for cre- dits	1 writte	n examinatio			/			
Media and methods	Selbsts						C C	
Literature		on den einzelr	nen Doze	nten the	eme <u>ns</u> pe	zifisch	genannt	
Further information	1							

Module description	Processing of Materials							
Signature	MaMawi-22-01; MaAFM-22-	01, MaPhy-	42-05					
Semester and recurren- ce	2 nd / summer term							
Responsible for module	Prof. Dr. Haider							
Lecturer	Prof. Dr. Haider Prof. Dr. Horn Prof. Dr. Ruhland Prof. Dr. Stritzker Prof. Dr. Wixforth (SS 2011)							
Language	english							
Curriculum inclosures	Master of Materials Science Materials, Master Physics		y module),		d Functional			
Lecture type and hours		SWS 3		Group size	_			
		Presence time	Self- study	Total				
	Vorlesung	56	56	112				
	Klausur	2	40	42				
				154	-			
	5							
Work load (hours)	none							
	Grundkenntnisse der Materia	alwissensch	aften					
Acquired skills and knowledge	für die unterschi Dünnschichtmate beherrschen nebe lang eher im Lab besitzen die Kom	 kennen die wichtigsten Methoden der Materialbe- und -verarbeitung für die unterschiedlichen Klassen von Materialien – Halbleiter, Dünnschichtmaterialien, Polymere, Metalle, Verbundmaterialien, beherrschen neben industriellen Verfahren auch Methoden, die bis- lang eher im Labormassstab realisisert sind und besitzen die Kompetenz, aktuelle Problemstellungen aus dem obengenannten Themenbereich selbständig zu bearbeiten. 						
Content	2.2.3. carbon fibe	lymers vior of Polym ner Melts og (Fibers, F olymer Proc ating, Foamin te materials perties of s perties of fib nforced poly reinforced poly reinforced poly reinforced poly reinforced s s on: n ion ersion-Ionim	ilms) iesses ng) per reinforce mers polymers d ceramics ed ceramics					

3.2.1. Ion Beam Techniques 3.2.2. X-ray Diffraction 3.2.3. X-ray Diffraction 3.2.4. Scaling of Semiconopoils 3.2.5. Magnetooptics 3.2.6. Optical, electrical, mechanical Properties 4. Processing of Semiconductors 4.1. crystal growth and epitaxy 4.1.1. crystal growth techniques, molecular beam-, liquid phase- and gas phase epitaxy, surface preparation 4.2. oxidation and lithography 4.2.1. thermal and pyrolithic oxidation 4.2.2. oxidation and lithography 4.3.1. diffusion doping, masking with oxide layers, ion implantation, factorial of othmic contacts 4.3. etching processes 4.4.1. diffusion doping, masking with oxide layers, ion implantation, factorial of othmic contacts 4.5. complete processes 4.5.1. process steps for fabrication of planar devices and integrated circuits 4.6. cleanrooms 4.6. cleanrooms 4.6. 1. eharacteristics of metals 5.1. Basics 5.1. Basics 5.1. Basics 5.2.1. solidification 5.2.2. rapid solidification 5.2.3. thermodynamics 5.2.4. soldering, welding 5.3. tool forming 5.3. tool forming 5.3. tool forming, forging 5.3. tool forming, regrass 5.3. thisoforming 5.3. thisoforming <td< th=""><th></th><th>0.0. This Files Observations</th></td<>		0.0. This Files Observations
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Modulo description	Theoretica	Concon	te and S	imulati	<u></u>					
Module description Signature	Theoretical Concepts and Simulation MaMawi-23-01; MaAFM-23-01									
Semester and recur-										
rence	2 nd semest	2 nd semester / each summer term								
Responsible for module	Dr Schuste	Dr. Schuster								
Lecturer		Prof. Dr. Chioncel (SS 2011)								
Language	english		0 2011)							
Language	Crigiion									
Curriculum inclosures		Master Materials Science (compulsory module), Master Advanced Functional Materials (compulsory module)								
		Туре		SWS		Group	size			
Lecture type and hours		Lecture		3		40				
		Project		1		20				
			Presen	ice	Self-s	tudu	Total			
			time		Sell-S	luuy	TOLAT			
Work load	Lectu	ure	45		30		75			
(hours)	Proje	ect	15		60		75			
``		entation			30		30			
							180			
Credit points	6		1		1			1		
Prerequisites acc. to	-									
the regulations of study	none									
	Basic know	ledge of c	uantum	mechar	ics, the	modyna	mics, and num	erical me-		
Recommended prere- quisites	thods as we					,	,			
quisites				Ũ	0 0					
Acquired skills and knowledge	 They have the expertise to find the numercal method approriate for the problem and to judge the quality and validity of the numerical results. Integrated acquirement of soft skills: independent handling of hard- and ware while using English documentations, ability to investigate abstract cumstances with the help of a computer and present the results in write oral form, capacity for teamwork 						ults. rd- and soft- bstract cir-			
Content	tools 2. Basic nu 3. Ordinary	umerical m v and Partinger equation ar Dynami	nethods: i ial Differe tion) cs	interpola	ation, inf	egration	uages, data vi ífusion equatio			
Requirements for cre- dits	20 pages) a	as well as	an oral p	presenta	ition		nary of the res	·		
Media and methods	Blackboard presentatio ment a give	ns; in the	project w	ork with	/ supple n a comp	mented outer in c	by beamer or o order to numer	overhead ically imple-		
Literature	Press) 2. J. M. 1 3. Koonii 4. D. C. I Univer	 Tao Pang, An Introduction to Computational Physics (Cambridge University Press) J. M. Thijssen, Computational Physics (Cambridge University Press) Koonin, Meredith, Computational Physics (Addison-Weseley) D. C. Rapaport, The Art of Molecular Dynamics Simulation, (Cambridge University Press) W. H. Press et al, Numerical Recipes (Cambridge University Press) 								
Further information	Links to sof	ftware rela	ated to th	e cours	e:					
	- http://wwv									

 http://www.cplusplus.com/doc/tutorial/ http://www.cygwin.com/ http://xmd.sourceforge.net/download.html http://www.rasmol.org/ http://felt.sourceforge.net/ 	
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Module description	Metho	od Course: Ele	ctron	Microscopy	1					
Signature		MaMawi-24-02, MaAFM-24-02								
Semester and recurren-		2 nd / summer term								
Responsible for module	Prof.	Prof. Dr. Haider								
Lecturer		Prof. Dr. Haider								
Language	englis									
Curriculum inclosures			terials	Science: M	aster Advan	ced F	unctional Materia	als		
		ype	atoriaic	SWS			up size			
Lecture type and hours		/lethodenkurs		6		3-4	"p 0. <u>=</u> 0			
			Pres	sence time	Self-study	• ·	Total			
	V	/orlesung	24		48		72			
Work load		Praktikum	48		48		96			
(hours)		rotokoll	-		50		50			
							218			
Credit points	8									
Prerequisites acc. to the regulations of study	none									
Recommended prerequi- sites		nisse der Festk								
Acquired skills and knowledge	elektro Hierzu behan werde schieo entsch	In diesem Kurs werden die wichtigsten Grundlagen und Verfahren der Raster- elektronenmikroskopie und Transmissionselektronenmikroskopie vermittelt. Hierzu werden in je zweiständigen Vorlesungen die theoretischen Grundlagen behandelt, die anschließend in praktischen Übungen an den Geräten vertieft werden. Die Studierenden werden in die Lage versetzt, Materialien mittels ver- schiedener elektronenmikroskopischer Techniken zu charakterisieren bzw. zu entscheiden, ob der Einsatz dieser Techniken für bestimmte Fragestellungen sinnvoll ist.								
Content	1 2 3 4 5 6 7 Exerci 8 9 1 1 TEM: Lectur 1 2 3 4 5 6 7 8	 SEM: Lectures Layout of Electron Microscopes and Electron Optical Components Electron Solid Interactions Contrast Formation in Scanning Electron Microscopy (SEM) SE/BSE contrast Electron Back Scattering Diffraction (EBSD) Analytical techniques Special Applications of SEM Exercises Sample preparation: cutting, polishing and etching Introduction to the SEM instrument Modes of imaging Energy Dispersive X-ray Spectroscopy (EDX) TEM: Lectures TEM specimen preparation techniques Components of a TEM, principle lens design, lens aberrations Electron diffraction: fundamentals Contrast formation at bright field, dark field, weak beam dark field, and many beam conditions, "chemical" imaging Bright field, dark field, weak beam dark field imaging of dislocations Kinematical theory of electron wave propagation in crystals, Howie Whelan equations, contrast of defects High resolution TEM, lattice imaging of crystals Advanced diffraction techniques: Kikuchi patterns, HOLZ lines and Convergent Beam Diffraction (CBED) 								

	Exercises
	 Visit to TEM Labs, preparation of AI samples, preparation of Si plan view samples TEM inspection of AI samples at TEM, fundamental alignements Recording of single crystalline diffraction patterns, indexing of diffraction spots, calibration of camera length & image rotation Observation of stacking faults, thickness fringes, strain contrast in crystalline samples Lattice imaging of a compound semiconductor Observation of Kikuchi patterns Recording of elemental maps
Requirements for credits	Bericht (jeweils ein Bericht pro Gruppe)
Media and methods	
Literature	 D.B.Williams and C.B.Carter Transmission Electron Microscopy Plenum Press, New York/London, 1996 M.A. Hirsch, A. Howie, R. Nicholson, D.W. Pashley, M.J. Whelan Electron microscopy of thin crystals Krieger Publishing Company, Malabar (Florida), 1977 L. Reimer Transmission electron microscopy Springer Verlag, Berlin/Heidelberg/New York, 1984 P.J. Goodhew Thin foil preparation for electron microscopy Elsevier, Amsterdam, 1985 P.R. Buseck, J.M. Cowley, L. Eyring High-resolution transmission electron microscopy Oxford University Press, 1988 E. Hornbogen, B. Skrotzki Werkstoff-Mikroskopie Springer Verlag, Berlin/Heidelberg/New York, 1995 In situ scanning electron microscopy in materials research Klaus Wetzig, AkadVerl., 1995 Scanning electron microscopy Ludwig Reimer, Springer Verlag, 1985 Scanning electron microscopy Ludwig Reimer, Springer Verlag, 1985 Elektronenmikroskopie Stanley L. Flegler ; John W. Heckman ; Karen L. Klomparens Spektrum, Akad. Verl., 1995
Further information	-

Modul description	Method Course: Elec	tronics	for Physici	sts and Materi	ials Scientists				
Signature	MaMawi-24-04; MaAFM-24-04								
Semester and recur- rence	1 st semester / each term								
Responsible for module	Prof. Dr. Wixforth								
Lecturer	Dr. Hörner (SS 2012)								
language	english	english							
Curriculum inclosures		Master Material Science; Master Advanced Functional Materials							
	type		SW/S	Group size	е				
Lecture type and hours	lectures tutorial		<u>3</u> 1	20					
	Practical		I	20					
	course		2,5	20					
		Prese	ence time	Self-study	Total				
	lectures	45		40	85				
Work load	tutorial	15		40	55				
(hours)	homework			50	50				
	Practical course	40		10	50				
					240				
Credit points	8								
Prerequisites acc. to the regulations of study	none								
Recommended prere- quisites	none								
Acquired skills and knowledge	 engineering for the use in the Lab, have skills in easy circuit design, measuring and control technology, analog and digital electronics have expertise in independent working on circuit problems. They can calculate and develop easy circuits. 								
Content	 Basics in electronic and electrical engineering [4] Quadrupole theory [2] Analog technique, transistor and opamp circuits [5] Boolean algebra und logic [4] Digital electronics and calculation circuits [6] Microprocessors and Networks [4] Basics in Electronic [8] Implementation of transistors [8] Operational amplifiers [8] Digital electronics [8] Practical circuit arrangement [8] 								
Requirements for cre- dits	Oral examination (max		,						
Media and methods		lectures: slides/blackboard talk with help of other media and experiments tutorial: pratical circuit design self-study							
Literature	 Paul Horowitz: The National Instrumen 					rlesung)			
Further information	The lecture Electro ER with the lab cou Course Electronic	urse will	be awarded	l by credit point	s for the Metho				

Module description	Method Course	: Materials S	ynthes	is				
Signature	MaMawi-24-05; MaAFM-24-05							
Semester and recur-	1 st or 3 rd Semester / winter term							
rence								
Responsible for module	Prof. Dr. Scherer							
Lecturer	Prof. Dr. Schere	r, Co-workers	5					
language	english							
Curriculum inclosures	Master Materials	s Science; Ma					1	
	Туре		SWS		Group	size		
Lecture type and hours	Practical co	ourse	4		4			
	Lecture							
			2	0.11	8	T ()		
		Presence	time	Self-s	study	Total	_	
	Practical	60		90		150		
Work load	course			00				
(hours)	Lecture	30		30		60		
	Exam	_		30		30		
One dit is a justa						240		
Credit points	8							
Prerequisites acc. to	none							
the regulations of study	The prestical co	una ia haaad	a 10 4 10 a	م م م م م				
Recommended prere-	The practical con					stry I, Chemis	try II, Chemi-	
quisites	stry III and the p	ractical cours	e in phy	/sical ch	emistry			
	The student							
	The student							
	Gains basic p							
Acquired skills and	lytical method							
knowledge	via X-ray diffr) as well as	
	physical meth	nods (e.g. the	rmoelec	tric prop	perties, n	nagnetism).		
	 Possesses th 	e ability to pe	rform m	naterials	synthes	es under instr	ruction	
	 is able to cho 	ose the appro	opriate c	characte	rization r	nethod for the	e materials.	
			•					
	Content of the p							
	synthesis and ch	naracterisatio	n of the	followin	g functio	nal materials:		
	 Organic Poly 	/mers [4+2]						
	 Zeolites and 	mesoporous	Materia	ls [4+2]				
Content	Porous Coor							
	 Ionic liquids 	[4+2]	-	-				
	Bio materials	[4+2]						
	Oxides "Sol-		ng and	ceramic	Methods	s" [4+2]		
	Lower dimen					. [–]		
	Ferrofluides				_1			
		[2 ' ']						
Requirements for								
credits	1 written examin	ation, 90 min						
Media and methods	Black board pres	sentation Re-	amer pr	esentati	on, Hand	louts		
	1. U. Schubert, I						VCH)	
	2. D. W. Bruce,							
	3. JP. Jolivet, N							
	State (John W		1011150	y anu S	ynu 18315		0110 0010	
Literature	4. W. Jones, C.N		ramolo	cular Or	nanizatio	n and Matari	als Design	
	(Cambridge U			cuiai Ul	yanizall	and water	ลอ มีชื่อเราไ	
	5. L.V. Interrante			ith Char	mistry of	Advanced M	atoriale. An	
	Overview (Wil			iiii, Chel	mistry of		ateriais – All	
	7. A. R. West, B		to Char	nietry (1		W& Sonal		
Further information		2310 30110 318		mony (J		y a 30115)		
	-							

Madula description	Mo	thad Courses Ma	thada	in Pionhyo	ioc					
Module description Signature		Method Course: Methods in Biophysics MaMawi-24-06; MaAFM-24-06								
Semester and recur-		,								
rence	eve	every term (upon agreement)								
Responsible for module	Pri	PrivDoz. Thalhammer								
Docent		PrivDoz. Thalhammer, Dr. Franke, Dr. Schmid (SS 2011)								
language		german/english								
Curriculum inclosures		Master Materials Science; Master Advanced Functional Materials, Master								
	Phy	Physics								
		Туре		SWS		Group size				
Lecture type and hours		lecture	•	4		20-30 3				
		laboratory cours		sence time	Self-study					
		lecture	45		40	85				
Work load		lab. course	40		15	55				
(hours)		exam	10		40	40				
		- Chain			10	180				
Credit points	8	1					•			
Prerequisites acc. to the	otto	ndance of the los	turo D	ionhygigg on	d Diamataria					
regulations of study	atte	endence of the lec	ture B	iopnysics an	lo Biomateria	ais				
Recommended prerequi-	nor									
sites	_	-								
Acquired skills and knowledge	pra	 the students know basic terms, concepts and phenomena in radiation biophysics aquire basic knowledge of fluidic and biophysical phenomena on small length scales and applications and technologies of microfluidic analystical systems learn skills in tissue culture and immun-histochemical staining procedures learn skills in fluorescence and confocal scanning microsopy learn skills to calculate fluidic problems on small length scales learn skills to handle microfluidic channel systems practical laboratory course and experiments: unit radiation biophysics concepts in radiation protection low-dose irradiation biophysics c. DNA repair dynamics of living cells after ionizing radiation d. confocal scanning laser microscopy 								
Requirements for credits	wor	 unit microfluidic a. microfluidic systems b. accoustic driven microfluidics c. calculation of microfluidic problems unit analysis 								
		rk (lab) report ture: transparencie	es/cha	Ikboard with	additional m	nedia and experime	ents			
Media and methods	exe	ercise: intensive m								
Literature	T. H ISB J. F Ienl S. H tion J. E ISB Iect	private study T. Herrmann, Klinische Strahlenbiologie – kurz und bündig, Elsevier Verlag, ISBN-13: 978-3-437-23960-1 J. Freyschmidt, Handbuch diagnostische Radiologie – Strahlenphysik, Strah- lenbiologie, Strahlenschutz, Springer Verlag, ISBN: 3-540-41419-3 S. Haeberle und R. Zengerle, Microfluidic platforms for lab-on-a-chip applica- tions, <i>Lab-on-a-chip</i> , 2007, 7 , 1094-1110 J. Berthier, Microdrops and digital microfluidics, William Andrew Verlag, ISBN:978-0-8155-1544-9 lecture notes								
Further information		course will partly uires attendance of				enter Munich. Lab c	course			

Modul description	Method Course: Opti	cal Properties of S	Solids					
Signature	MaMawi-24-07, MaAFM-24-07							
Semester and recur- rence	1 st -3 rd semester / each term							
Responsible for module	Prof. Dr. Loidl	Prof. Dr. Loidl						
Lecturer	Dr. Deisenhofer, Dipl	Phys. Schmidt, M.S	c. Wang (SS 20	011)				
language	English							
Curriculum inclosures	Master Material Science							
	type	SWS	Group size	е				
Lecture type and hours	lectures	2	Max. 9					
	tutorial							
	practical course	4	2 to 5					
		Presence time	Self-study	Total				
Work lood	lectures	30	35	65				
Work load (hours)	home work		30	30				
(nours)	practical course	60	35	95				
	protocol		50	50				
Ore dit rejet-				240				
Credit points Prerequisites acc. to	8							
the regulations of study	none							
Recommended prere-	Basic knowledge in so	lid state physics, ba	isic knowledge i	in electrodynam	nics and			
quisites	optics							
Acquired skills and knowledge								
Content (approximated duration in hours)	 Electrodynamics of solids (24) Maxwell equations Electromagnetic waves Refraction and Interference, Fresnel equations FTIR spectroscopy (30) Fourier transformation Michelson-Morley and Genzel interferometer Sources and detectors Submillimeter spectroscopy (12) Mach-Zehnder interferometer Backward-wave oscillators and detectors Terahertz Time Domain spectroscopy (12) Generation of pulsed THz radiation Gated detection, Austin switches Elementary excitations in solids (12) Infrared-active phonons Magnetic-dipole excitations Crystal-field excitations 							
Requirements for cre-	Written homework, writ	tten report on the e	experiments (ed	iting time 3 was	ks			
dits	max. 30 pages), short				,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,			

Media and methods	Media: Projector, slides, blackboard, web resources Methods: Lecture, exercises, teamwork, students' presentations				
Literature	 J.D. Jackson, Classical Electrodynamics (de Gruyter) N.W. Ashcroft, N.D. Mermin, Solid state physics (Saunders) Ch. Kittel, Introduction to solid state physics (Wiley) E. Hecht, Optics (Addison-Wesley Longman) 				
Further information	-				

Modul description	Method Course: Spectroscopy on Condensed Matter									
Signature	MaMawi-24-09, MaAFM-24-09									
Semester and recur-	1 st - 3 rd semester / each term									
rence Responsible for module	Prof. Dr. Loidl									
Lecturer	Dr. Krohns, M.Sc. Schrettle, DiplPhys. Wolf (SS 2011)									
language	English									
Curriculum inclosures		Master Material Science; Master Advanced Functional Materials								
	typ		, what	SWS	Group size					
Lecture type and hours		tures		2	9	0				
		orial		-	ŭ					
		actical		_						
	-	urse		4	3 x 3					
		ŀ	Prese	nce time	Self-study	Total				
	lectures	3	30		30	60				
Work load	tutorial									
(hours)	Practical co	urse 6	60		60	120				
	examination		2		24	26				
						236				
Credit points	8									
Prerequisites acc. to	-									
the regulations of study	none									
Recommended prere-	Basic knowledge	e in solid	state	physics, ba	sic knowledge	in physics of al	asses			
quisites	and supercooled			, , , , , , , , , , , , , , , , , , , ,		, , , g.	'			
Acquired skills and knowledge	 the investigation of the dielectric properties of condensed matter. are trained in planning and performing complex experiments. They learn to evaluate and analyze the collected data. are taught to work on problems in experimental solid state physics. This includes analysis of measurement results and their interpretation in the framework of models and theories. 									
Content	 6. Dielectric Spectroscopy [8] Methods Cryo-techniques Measurement quantities Relaxation processes Dielectric phenomena 7. Ferroelectric Materials [7] Mechanism of ferroelectric polarization Hysteresis loop measurements Dielectric spectroscopy 8. Glassy Matter [8] Introduction Glassy Phenomena Dielectric Spectroscopy 9. Multiferroic Materials [7] Introduction Microscopic origins of multiferroicity Pyrocurrent measurements Dielectric Spectroscopy 									
Requirements for cre- dits	1 examination (1			-						
Media and methods	lectures: slides/b self-study	blackboar	rd talk	with help o	of other media a	nd experiments	6			
Literature					erphysik (Olden rphysik (Oldenb					

	٠	C.J.F. Böttcher, P. Bordewijk, Theory of Electric Polarization (Elsevier)
	٠	J. R. Macdonald, Impedance Spectroscopy (Wiley)
	٠	H. Scholze, Glas (Springer)
	٠	S.R. Elliott, Physics of Amorphous Materials (Longman)
	٠	R. Zallen, The Physics of Amorphous Solids (Wiley)
Further information	-	

Modul description	Ме	Method Course: Thin Film Analysis with Ion Beams								
Signature	Ма	MaMawi-24-11, MaAFM-24-11								
Semester and recur-	2 rd	3 rd or 4 th semester / once a year								
rence		-								
Responsible for module	Priv	PrivDoz. Karl								
Docent										
language	Eng	glish								
Curriculum inclosures	Ma	Master Materials Science; Master Advanced Functional Materials								
			type		SWS	Group size	e			
Lecture type and hours			lectures		2	12				
			tutorial		N/A	N/A				
			Practical se	cour-	4	2-5				
					ence time	Self-study	Total			
Work load		lecture		30		30	60			
(hours)		tutoria								
(10013)			al course	60		80	140			
	report				40	40				
Credit points	8						240			
Prerequisites acc. to	0									
the regulations of study										
Recommended prere-										
quisites	Sol	id knowl	edge in soli	id state	and experin	nental physics				
Acquired skills and knowledge	•	films by	asic terms, ion beams			to plan and per	-			
Content	 Introduction to ion beam analysis techniques and concepts Rutherford backscattering spectroscopy Theory of particle scattering and cross-section Experimental setup Dynamic secondary ion mass spectroscopy (SIMS) Simulation and data evaluation of Rutherford backscattering spectrometry (RBS) experiments Experimental work in the laboratory in the Institute of Physics. Has to be conducted within 3 months. 									
Requirements for cre- dits	1 w	ritten re	port and se	minar t	alk					
Media and methods										
Literature	•	Will be provided by supervisor.								
Further information	-									

Madula description	Method Course: X-ray and Neutron Diffraction Techniques								
Module description Signature	MaMawi-24-12, MaAFM-24-12								
Semester and recur-									
rence	2 nd semester / summer semester								
Responsible for module	Prof. Dr. Scherer								
Lecturer	Prof. Dr. Scherer, Dr. Eickerling (SS 2011)								
Language	English								
Curriculum inclosures	Master Materials Science; Master Advanced Functional Materials								
	Type SWS Group size								
Lecture type and hours	practica								
	lecture	T _	2		8				
		Preser	nce	Self-s	tudy	Total			
	prostical source	time				150	_		
Work load	practical course lecture	60 30		90 30		150 60			
(hours)	examination	50		30		30			
	oxamination			00		240	_		
Credit points	8					1 2 . 0			
Prerequisites acc. to									
the regulations of study	none								
Recommended prere-	The practical cours	e is based	on the	module ,	"Chemis	ch-Physikalis	ches Prakti-		
quisites	kum"								
Acquired skills and knowledge	 gain basic practical knowledge on structural characterisation methods for s gle-crystalline and powder samples employing X-ray and neutron diffraction techniques have the skill to, under guidance, perform phase-analyses and structure de terminations are competent to analyze the structure-property relationships of new materials. 						n diffraction tructure de-		
Content	 Subjects of the practical training and the accompanying lecture are the theoretical basics and the practical application of X-ray and neutron diffraction techniques: Basic introduction to X-ray and neutron crystallography [4+2] X-ray/neutron scattering [4+2] Data collection and reduction techniques [4+2] Symmetry and space group determination [4+2] Structural refinements: (a) The Rietveld method (b) Difference Fourier synthesis [4+2] Structure determination: (a) Patterson Method (b) Direct Methods [4+2] Interpretation of structural refinement results [4+2] Electronic structure determination and analysis [2+1] 								
Requirements for cre-	1 written examination	on, approx	. 90 mir	า.					
dits Media and methods					ute				
						ffraction Ovfo	rd I Iniversity		
Literature	 blackboard and beamer presentations, handouts C. Hammond, The Basis of Crystallography and Diffraction, Oxford University Press Inc., New York, 2001. W. Clegg, A. J. Blake, R. O. Gould, P. Main, Crystal Structure Analysis, Principle and Practice, Oxford University Press Inc., New York, 2001. G. Giacovazzo, Fundamentals of Crystallography, Oxford University Press Inc., New York, 1994. R. A. Young, The Rietveld Method, Oxford University Press Inc., New York, 2002. W. Massa, Crystal Structure Determination, Springer, Berlin, 2004. 								
Further information	-		2.5		<i>,</i> -1	, ,			

Modul description	Method Course: Solid State Synthesis Lab									
Signature	MaMawi-24-13, MaAFM-24-13									
Semester and recur-			, 2 nd seme							
rence										
Responsible for module		Prof. Dr. Volkmer								
Lecturer		Prof. Dr. Volkmer, Prof. Dr. Höppe, Dr. Bredenkötter, Dr. Hanss (SS 2011)								
language		English / German								
Curriculum inclosures		Master Materials Science (elective module); Master Advanced Functional Mate- rials (elective module)								
Lecture type and hours			type		SWS	Group size	е			
			Method c	ourse	6	1-2				
				Prese	ence time	Self-study	Total			
	5	Semina	r	20		40	60			
Work load			al course	100		20	120			
(hours)		Homew		-		60	60			
	- <u>-</u>	1011101				00	240			
Credit points	8			I			210	1		
Prerequisites acc. to	_									
the regulations of study	None									
Recommended prere-										
quisites	None	None								
Acquired skills and knowledge	 us ac 	 use modern preparation techniques (e.g. microwave synthesis) acquire competence to work under inert conditions (Schlenk technique) 								
Content	top • pc • m(• ce • ch	 metal-organic precursor compounds ceramics, luminescent compounds 								
Requirements for cre- dits			, protocols							
Media and methods	Prese	entatior	n, publicatio	ons, se	f-study					
Literature	Chemical databasesPrimary literature (scientific articles and reviews)									
Further information	upon	reques	st							

Madula description	Method Course: Semiconductor and surface acoustic wave devices								
Module description Signature	MaMawi-24-14, MaAFM-24-14								
Semester and recur-									
rence	1st or 3rd Semester / winter term								
Responsible for module	Dr. H. Krenner								
Docent	Dr. H. Krenner								
Language	english								
Curriculum inclosures	Master Material Science; Master Advanced Functional Materials								
		Type SWS Group size							
Lecture type and hours		ecture	4			20-30			
	L	ab Course	1			1			
		Pre	sence	0	Self-st	tudy	Total		
		time)	, C		uuy	10101		
Work load	Lecture	45			10		85		
(hours)	Lab cours	se 40		1	5		55		
(10013)	Exam			4	10		40		
	Exam				10		-		
							180		
Credit points	8								
Prerequisites acc. to	Attendence of	lecture Phy	sics and	d Tech	nolog	v of Ser	niconductor [)evices"	
the regulations of study	7				molog	y ei eei			
Recommended prere-	Basic knowled	lae in solid-s	tate phy	sics ar	nd qu	antum n	nechanics		
quisites	Acquired skills								
Acquired skills and knowledge	 bandstructure, doping, carrier excitations and carrier transport Application of developed concepts (effective mass, quasi-Fermi levels) to decribe the basic properties of semiconductors Application of these concepts to describe and understand the operation pr ciples of semiconductor devices such as diodes, transistors and optically a tive elements (LEDs, detectors and lasers) Knowledge of the technologically relevant methods and tools in semiconductor micro- and nanofabrication Pratical application clean room fabrication techniques: sample preparation optical lithography, deposition methods, lift-off techniques, sample inspect Electrical and optical characterization of fabricated devices 						peration prin- optically ac- semiconduc- preparation,		
Content	excitations 2. Semicondu 3. Semicondu 4. Optoelectr	 Basic properties of semiconductors (electronic bandstructure, doping, carrier excitations and carrier transport) [10] Semiconductor diodes and transitors [8] Semiconductor technology [4] Optoelectronics [4] Surface acoustic wave (SAW) devices 							
Requirements for cre- dits	1 Written lab r	eport plus 1	written e	exam					
Media and methods	Lecture: slides Lab class: inte Self-study					media a	and experime	nts	
Literature	 Yu und Cardona: Fundamentals of Semiconductors (Springer) Sze: Physics of Semiconductor Devices (Wiley) Sze: Semiconductor Devices (Wiley) Madelung: Halbleiterphysik (Springer) Singh: Electronic and Optoelectronic Properties of Semiconductor Structures (Cambridge University Press) 								
Further information	Requires atter	ndence of "P	hysics a	nd Teo	chnol	ogy of S	emiconducto	Devices"	

Modul description	Me	Method Course: Characterization of Porous Materials							
Signature	Ma	MaMawi-24-15, MaAFM-24-15							
Semester and recur- rence	2 nd	2 nd semester							
Responsible for module	Pro	Prof. Dr. Volkmer							
Lecturer	Pro	Prof. Dr. Volkmer, co-workers							
language	Eng	English / German							
Curriculum inclosures		Master Materials Science (elective module); Master Advanced Functional Mate- ials (elective module)							
Lecture type and hours		•	type		SWS	Group size	9		
			Method c	ourse	6	1-2			
				Prese	ence time	Self-study	Total		
		Semina	ar	20		40	60		
Work load		Practic	al course	100		20	120		
(hours)		Homev	vork	-		60	60		
							240		
Credit points	8								
Prerequisites acc. to	No	None							
the regulations of study	NO								
Recommended prere- quisites	Leo	Lecture Porous Materials (MaMawi-41-18, MaAFM-41-18)							
Acquired skills and knowledge		 The students will learn how to use modern solid state preparation techniques (e.g. microwave synthesis) employ analytical methods dedicated to porous materials 							
Content		 Zeolites) Characterization methods Thermal Analysis (TGA; EGA) Structure Determination (XRD, VTXRPD) Absorption and Diffusion (BET, BET isotherms) 							
Requirements for cre- dits			•			eport (editing tir	me 1 week)		
Media and methods	Slic	es/black	board, face	e to face	e tutorial, sel	f-study			
Literature	•	Various. Will be provided by supervisor							
Further information	upo	on reque	st						

3. Materials Science Seminar

Module description	Introduct	Introduction to Materials								
Signature	MaMawi-3	81-01, Ma	AFM-31-	01						
Semester and recur-	1 st somest	st semester / Winter term								
rence										
Responsible for module	Prof. Dr.	Prof. Dr. Haider								
Lecturer										
Language		English								
Curriculum inclosures	Master of	Master of Science Materials Science; Master Advanced Functional Materials								
Lecture type and hours		Туре		SWS		Group	size			
Lookaro type and nearo		Semina		2		20				
Work load		Presence time Self-study Total								
(hours)	Semina	ar	28		80		108			
Credit points	4						1	1		
Prerequisites acc. to the regulations of study	None	None								
Recommended prerequi- sites	Knowledg	Knowledge of basic materials science								
Acquired skills and knowledge	•	materials								
Content	Varying to quirement						o scope, app aterials	lication, re-		
Requirements for credits	presentati	on with te	erm papel	r of 30-4	l5 min					
Media and methods	Powerpoir	nt present	tation							
Literature	specific fo	r each top	oic, to be	gathere	d by the	e student	ts			
Further information										

4. Specialization in Materials Science

Module description	Physics and Technology of Semiconductor Devices										
Signature	MaMawi-41-01, MaAFM-41-01, BaMawi-64-01, MaPhy-24-01										
Semester and recur-	1 st or 3 rd Semester / every winter term										
rence											
Responsible for module	Prof. Dr. Wixforth										
Lecturer	K I-										
Language	english Master Material Science; Master Advanced Functional Materials; Master Physics										
Curriculum inclosures		(elective module)									
	(elective int	Type SWS Group size									
Lecture type and hours		Lecture		3		20	0.20	_			
51		Tutorial		1		20					
			Presen	ce	Self-s	tudy	Total				
			time			luuy					
Work load	Lectur		45		40		85	_			
(hours)	Tutoria	al	15		40		55	_			
	Exam				40		40				
							180				
Credit points	6		1		1		100				
Prerequisites acc. to											
the regulations of study	none										
Recommended prere-	Basic know	ladaa in a	alid atat	nhunin			nachanica				
quisites	Acquired sk	•	ullu-state	e priysic:	s anu qu	Janum	nechanics				
Acquired skills and knowledge	 Basic knowledge of soid-state and semiconductor physics such as electronic bandstructure, doping, carrier excitations and carrier transport Application of developed concepts (effective mass, quasi-Fermi levels) to decribe the basic properties of semiconductors Application of these concepts to describe and understand the operation principles of semiconductor devices such as diodes, transistors and optically active elements (LEDs, detectors and lasers) Knowledge of the technologically relevant methods and tools in semiconductor micro- and nanofabrication 										
Content		ons and canductor di nductor di	arrier trar odes and chnology	nsport) [′ d transito	10]	ronic bar	ndstructure, d	oping, carrier			
Requirements for cre- dits	1 Written ex	,	,								
Media and methods	Lecture: slic Tutorial: inte Self-study					r media a	and experime	nts			
Literature	 Yu und Cardona: Fundamentals of Semiconductors (Springer) Sze: Physics of Semiconductor Devices (Wiley) Sze: Semiconductor Devices (Wiley) Madelung: Halbleiterphysik (Springer) Singh: Electronic and Optoelectronic Properties of Semiconductor Structures (Cambridge University Press) 										
Further information											

Module description	Nanostructures / Nanophysics									
Signature	MaMawi-41-02, MaAFM-41-02, MaPhy-24-02									
Semester and recur- rence	2 nd Semester / ever	y summer	term							
Responsible for module	Prof. Dr. Wixforth									
Lecturer	Dr. Krenner, Prof. Dr. Wixforth (SS 2011)									
Language	english									
Curriculum inclosures		Master Materialwissenschaften; Master Advanced Functional Materials; Master Physics (elective module)								
	Туре		SWS		Group	size				
Lecture type and hours	Lectur Tutoria	Lecture 3 2 Tutorial 1 2					-			
Work load	Lecture	Preser time 45	nce	Self-s	tudy	Total 85	_			
(hours)	Tutorial	15		40		55				
(Exam			40		40				
						180	1			
Credit points	6	1		I		1.00				
Prerequisites acc. to the regulations of study	none									
Recommended prere- quisites	Knowledge of quant	um mech	anics an	d semic	onductor	physics				
Acquired skills and knowledge	 Basic knowledge oft he fundamental concepts in modern nanoscale science Profound knowledge of low-dimensinal semiconductor structures and how these systems can be applied for novel functional devices for high-frequency electroncis and optoelectronics Konwledge of different fabrication approaches using bottom-up and top-down techiques Application of these concepts to tackle present problems in nanophysics 									
Content	 tems [5] Magnetotransportized conductant Optical propertiem modern optoeled Nanowires, Cart Nanophotonics, 	 Semiconductor quantum wells, wires and dots, low dimensional electron systems [5] Magnetotransport in low-dimensional systems, Quanten-Hall-Effect, Quantized conductance [5] Optical properties of quantum wells and quantum dots and their application in modern optoelectonic devices [5] Nanowires, Carbon Nanotubes, Graphen [3] Nanophotonics, photonic band gap materials, photonic crystals Emerging concepts such as Quantum Computing und Quantum Information 								
Requirements for cre- dits	1 written exam, 90 r	nin								
Media and methods	Lecture: slides/black Tutorial: intensive s Self-study	upport in s	small gro	oups			nts			
Literature	 Yu und Cardona: Fundamentals of Semiconductors Singh: Electronic and Optoelectronic Properties of Semiconductor Structures (Cambridge University Press) Davies: The Physics of Iow-dimensional Semiconductors (Cambridge University Press) V. V. Mitin et al.: Quantum Mechanics for Nanostructures (Cambridge University Press) Yariv: Quantum Electronics (Wiley) Journal and review articles on current topics in nanoscience 									
Further information										

Module description	Electronics for Physicists and Material Scientists								
Signature					-03, BaMawi-6	4-02			
Semester and recur-	1 st semester /		aastar						
rence	i semester/	each sen	lester						
Responsible for module	Prof. Dr. Wixfe	orth							
Lecturer	Dr. Hörner (S	S 2012)							
Language	English								
Curriculum inclosures	Master Materi	al Scienco	e (elec	tive module)	; Master Advar	nced Functional M	ate-		
Cumculum inclosules	rials								
		Туре		SWS	Group siz	e			
Lecture type and hours	lectures 3 20								
	<u> t</u>	tutorial		1	20				
				ence time	Self-study	complete			
Work load	lectures		45		40	85			
(hours)	tutorial		15		40	55			
(10013)	homewor	rk			50	50			
						190			
Credit points	6								
Prerequisites acc. to	none								
the regulations of study	none								
Recommended prere-	none								
quisites									
Acquired skills and knowledge	 engineering for the use in the Lab, have skills in easy circuit design, measuring and control technology, analog and digital electronics have expertise in independent working on circuit problems. They can calculate and develop easy circuits. 								
Content	 Basics in e Quadrupoi Analog tec Boolean a Digital elee Microproce Basics in B Implement Operationa Digital eleita 	le theory chnique, tr Igebra un ctronics a essors an Electronic tation of tr al amplifie	[2] ransist d logic nd calo d Netw [8] ransisto ers [8]	or and opam [4] culation circu vorks [4]	np circuits [5]				
Requirements for cre- dits	Oral examinat	tion (max.	15 mi	n.)					
Media and methods	lectures: slides/blackboard talk with help of other media and experiments tutorial: pratical circuit design self-study								
Literature					Cambridge Uni e package (erh	versity Press) altlich in der Vorle	esung)		
Further information	Scientists (co	ombined	lab co	urse AND l	ecture) exclude	icists and Mater es credit points for tists SEPERATE	the		

Signature MaMawi-41-04, MaAFM-41-04, MaPhy-24-04 Semester and recur- rence 2 nd Semester / every term Responsible for module PrivDoz. Thalhammer Docent PrivDoz. Thalhammer, Dr. Franke, Dr. Schmid (SS 2011) Language english Curriculum inclosures Master Materials Science (elective module); Master Advanced Furials; Master Physics Lecture type and hours Type SWS Group size Lecture type and hours Iecture 4 20-30 Work load (hours) Iecture 45 40 85 User Advanced Furies iab. course Iecture 4 20-30 Iab. course Iecture 45 40 85 (hours) Iecture 45 40 40 Iab. course Iex Iex Iex Iex Recommended prerequisites acc. to the regulations of study none Iex Iex Iex Acquired skills and knowledge Iex Iex Iex Iex Iex Iex Acquired skills and knowledge Iex Iex Iex Iex Iex Iex Iex<	Madula deservición	Dianhuaiaa and	Diamataria										
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rence 2 Semester / every term Responsible for module PrivDoz. Thalhammer, Dr. Franke, Dr. Schmid (SS 2011) Language english Curriculum inclosures Master Materials Science (elective module); Master Advanced Furials; Master Physics Lecture type and hours Type SWS Group size Lecture type and hours Type SWS Group size Work load (hours) Iecture 45 40 85 Ib. course ime 40 40 40 Verificit points 6 none none 125 Credit points 6 none none 125 125 Credit points 6 none none 125 125 Acquired skills and knowledge none mechanics, thermo dynamics, statistical physics 1 125 Acquired skills and knowledge 1.1 radiation protection 1.2 radiation radiation radiation radiation rabiotechnology, membranes and neuronal networks adapt skills in the independent processing of problems and de literature. They will be able to translate a biological oberserva ical question. 1.1 radiation protection				74, iviaPr	iy-24-04								
Tende PrivDoz. Thalhammer. Docent PrivDoz. Thalhammer. Dr. Franke, Dr. Schmid (SS 2011) Language english Master Materials Science (elective module); Master Advanced Furals; Master Physics Curriculum inclosures Ifype SWS Group size Lecture type and hours Ifype SWS Group size Work load Iab. course 4 20-30 (hours) Iab. course 4 40 40 Presence Self-study Total iab. course 4 40 40 (hours) 6 Presence 125 Prerequisites acc. to the regulations of study none mechanics, thermo dynamics, statistical physics Recommended prere- quisites mechanics, thermo dynamics, statistical physics 1 Acquired skills and knowledge 1. radiation in the lobpolymer-theory, microfibiological phy learn models of the (bio)polymer-theory, microfibiolic, radiation nanobiotechnology, membranes and neuronal networks 1. radiation in the independent processing of problems and de literature. They will be able to translate a biological observa ical question. 2. I havier-Stokes equation 2. I havier-Stokes equation 2. radiation in the low-dose reg		2 nd Semester / ev	very term										
Docent Prix-Doz. Thalhammer, Dr. Franke, Dr. Schmid (SS 2011) Language english Curriculum inclosures Master Materials Science (elective module): Master Advanced Funis; Master Physics Lecture type and hours If yoe SWS Group size Work load (hours) Image: Presence line Self-study Total Work load (hours) Image: Presence line Self-study Total Credit points 6 Presence line 125 Prerequisites acc. to the regulations of study none mechanics, thermo dynamics, statistical physics Acquired skills and knowledge Image: Presence line 125 Acquired skills and knowledge Image: Presence line 125 1 radiation protection none 1 radiation protection 125 1 radiation protection none 4 eam basic terms, concepts and phenomena of biological phy lear models of the (biolopolymer-theory, microffluidic, radiation nanobiotechnology, membranes and neuronal networks 4 lear basic terms, concepts and phenomena of biological phy lear models of the biolopolymer theory, microffluidic, radiation nanobiotechnology, membranes and neuronal networks			-										
Language english Curriculum inclosures Master Materials Science (elective module); Master Advanced Firals; Master Physics Lecture type and hours Image: Science (elective module); Master Advanced Filecture Work load (hours) Image: Science (elective module); Master Advanced Filecture Work load (hours) Image: Presence intervent Master Materials Isc. course Image: Presence intervent Master Materials Iab. course Image: Presence intervent Master Materials Recommended prerequisites acc. to the regulations of study mechanics, thermo dynamics, statistical physics Recommended prerequisites mechanics, thermo dynamics, statistical physics • Ieam models of the (bio)polymer-theory, microfluidic, radiation nanobiotechnology, membranes and neuronal networks • Ieam models of the (bio)polymer-theory, microfluidic, radiation nanobiotechnology, membranes and neuronal networks • Iaab. on-a-Chi py systems • Iaab. on-a-Chi py systems • Iaab. on-a-Chi py systems • <td></td> <td></td> <td></td> <td></td> <td></td> <td>: 1 /00 /</td> <td>244</td> <td></td>						: 1 /00 /	244						
Curriculum inclosures Master Materials Science (elective module); Master Advanced Furials; Master Physics Lecture type and hours Type SWS Group size Uecture type and hours Type SWS Group size Work load (hours) Presence 4 20-30 Uecture 4.5 40 85 Iab. course 40 40 40 Iecture 4.5 40 85 Credit points 6 7000 7010 Recommended prerequisites acc. to the regulations of study none mechanics, thermo dynamics, statistical physics Acquired skills and knowledge the students Iearn basic terms, concepts and phenomena of biological phy ilearn models of the (bio)polymer-theory, microfluidic, radiation nanobiotechnology, membranes and neuronal networks a dapt skills in the independent processing of problems and do literature. They will be able to translate a biological oberserva ical question. 1.1 1.1 radiation in the low-dose regime 1.3 1.3 radiation in the low-dose regime 1.4 1.2 Ird ation protection 1.4 2.4 1.4 Lab-on-a-Chip systems 3.1 1.5 2.4			ammer, Dr. I	-ranke, L	Jr. Schm	nia (55 2	2011)						
Connection Type SWS Group size Lecture type and hours Type SWS Group size Work load (hours) Iecture 4 20:30 Work load (hours) Iecture 45 40 85 Ib. course 40 40 40 Ib. course 40 40 40 Ib. course 40 40 40 Credit points 6 Prerequisites acc. to the regulations of study none Recommended prere- quisites mechanics, thermo dynamics, statistical physics the students • learn basic terms, concepts and phenomena of biological phy earn models of the (bio)polymer-theory, microfluidic, radiation nanobiotechnology, membranes and neuronal networks • learn basic terms, concepts and phenomena of biological physics 1.1 radiation biophysics 1.2 radiation in the low-dose regime 1.3 radiation protection 1.4 energy transfer in biological systems 1.5 biophysical concepts and biological response to ionizing 2.1 microfluidics 2.1.1 natural radiation 1.2 radiation	Language		0 : ()					· • • • • •					
Lecture type and hours Image: Type SWS Group size Work load (hours) Iab. course 20-30 Vork load (hours) Image: Type Self-study Total Iecture 45 40 85 Iab. course Image: Type Self-study Total Iecture 45 40 85 Iab. course Image: Type Image: Type Image: Type Presequisities acc. to the regulations of study none Image: Type Image: Type Recommended prer- quisites the students Image: Type Image: Type Image: Type Acquired skills and knowledge the students Image: Type Image: Type Image: Type Image: Type I adapt skills in the independent processing of problems and de literature. They will be able to translate a biological byse Image: Type Image: Type Image: Type I adapt skills in the independent processing of problems and de literature. They will be able to translate a biological systems Image: Type Image: Type I adapt skills in the independent processing of problems and de literature. They will be able to translate a biological response to ionizing	Curriculum inclosures			ective m	odule); N	/laster A	dvanced Fund	tional Mate-					
Lecture type and hours Index. course 20-30 Work load (hours) Intervention Presence ime Self-study Total Iecture 45 40 85 Iab. course Intervention 40 40 Iab. course Intervention 125 125 Credit points 6 Intervention 125 Credit points 6 Intervention 125 Recommended prerequisites mechanics, thermo dynamics, statistical physics Intervention 125 Recommended prerequisites Ites students Ites students<				014/0		0	- !						
Work load (hours) Iab. course Presence time Self-study Total Iecture 45 40 85 Iab. course - - - Credit points 6 - - - Prerequisites acc. to the regulations of study none - - - Recommended prere- quisites - - - - - Acquired skills and knowledge - Iearn basic terms, concepts and phenomena of biological phy elearn models of the (bio)polymer-theory, microfluidic, radiation nanobiotechnology, membranes and neuronal networks - - - • learn basic terms, concepts and phenomena of biological phy elearn models of the (bio)polymer-theory, microfluidic, radiation nanobiotechnology, membranes and neuronal networks - - • learn basic terms, concepts and phenomena of biological oberserva ical question. - - 1. radiation biophysics - - - - 1.1 radiation protection - - - - 1.2 radiation protection - - - <td< td=""><td>Lesting the second barries</td><td></td><td></td><td></td><td></td><td></td><td>SIZE</td><td>_</td></td<>	Lesting the second barries						SIZE	_					
Work load (hours) Presence time Self-study Total Iecture 45 40 85 ibb. course 40 40 40 exam 40 40 40 exam 40 40 40 credit points 6 none 125 Credit points 6 none mechanics, thermo dynamics, statistical physics Recommended prere- quisites mechanics, thermo dynamics, statistical physics the students iearn models of the (bio)polymer-theory, microfluidic, radiation nanobiotechnology, membranes and neuronal networks adapt skills and knowledge • learn basic terms, concepts and phenomena of biological phy iearn models of the (bio)polymer-theory, microfluidic, radiation nanobiotechnology, membranes and neuronal networks adapt skills in the independent processing of problems and de literature. They will be able to translate a biological oberserva ical question. adapt skills in the independent processing of problems and de literature. They will be able to translate a biological systems 1.5 tophysical concepts and biological response to ionizing 2.1 microfluidics 2.1 Navier-Stokes equation 2.2 the Rouse model 3.2 dynamic properties of polymers 3.1	Lecture type and nours			4		20-30		_					
Work load (hours) time Self-Study Total lecture 45 40 85 iab. course - - - exam 40 40 - Credit points 6 - - Prerequisites acc. to the regulations of study none - - Recommended prere- quisites mechanics, thermo dynamics, statistical physics - - Acquired skills and knowledge - - - - - Acquired skills and knowledge -		lab.			T		-						
Work load (hours) Interve 45 40 85 Iab. course interve			Self-study Lotal										
(hours) Image: Constant of the state													
exam 40 40 Credit points 6 Prerequisites acc. to the regulations of study none Recommended prere- quisites mechanics, thermo dynamics, statistical physics Acquired skills and knowledge the students • learn models of the (bio)polymer-theory, microfiludic, radiation nanobiotechnology, membranes and neuronal networks • adapt skills in the independent processing of problems and de literature. They will be able to translate a biological oberserva ical question. 1. radiation biophysics 1.1 natural radiation 1.2 radiation in the low-dose regime 1.3 radiation protection 1.4 energy transfer in biological systems 1.5 biophysical concepts and biological response to ionizing 2.11 Navier-Stokes equation 2.2 life at low Reynolds numbers 2.3 microfiludics 2.1 Navier-Stokes equation 2.2 life at low Reynolds numbers 3.3 reptation 3.4 viscoelastic networks Content 3.4 viscoelastic networks 4 membranes 5.1 thermodynamics and fluctuation 5.2 thermodynamics of interfaces 5.3 phase transition – 2 state model 5.4 nembrane elasticity 5 neuronal networks 7.1 ion channels 7.2 ion transport 7.3 electro physiology 7.4 dynamic neuronal processes			45		40		85						
Credit points 6 Prerequisites acc. to the regulations of study none Recommended prere- quisites mechanics, thermo dynamics, statistical physics Acquired skills and knowledge • learn basic terms, concepts and phenomena of biological phy • learn models of the (bio)polymer-theory, microfluidic, radiation nanobiotechnology, membranes and neuronal networks • adapt skills in the independent processing of problems and de literature. They will be able to translate a biological oberserva ical question. 1. radiation biophysics 1.1 natural radiation 1.2 radiation in the low-dose regime 1.3 radiation protection 1.4 energy transfer in biological systems 1.5 biophysical concepts and biological response to ionizing 2. microfluidics 2.1 Navier-Stokes equation 2.2 life at low Reynolds numbers 2.3 microfluidics 2.1 havier-Stokes equation 3.1 the Rousse model 3.2 the Zimm model 3.3 reptation 3.4 viscoelastic networks 4. membranes 5.1 thermodynamics of interfaces 5.3 phase transition – 2 state model 5.4 membrane elasticity 5. neuronal networks 7.1 ion channels 7.2 ion transport 7.3 electro physiology 7.4 dynamic neuronal processes	(hours)	lab. course											
Credit points 6 Prerequisites acc. to the regulations of study none Recommended prere- quisites mechanics, thermo dynamics, statistical physics Acquired skills and knowledge the students • learn basic terms, concepts and phenomena of biological phy elarn models of the (bio)polymer-theory, microfluidic, radiation nanobiotechnology, membranes and neuronal networks • adapt skills in the independent processing of problems and de literature. They will be able to translate a biological oberserva ical question. 1. radiation biophysics 1.1 radiation protection 1.2 radiation protection 1.4 energy transfer in biological systems 1.5 biophysical concepts and biological response to ionizing 2. microfluidics 2.1 Navier-Stokes equation 2.2 life at low Reynolds numbers 2.3 microfluidic phenomena 2.4 Lab-on-a-Chip systems 3. dynamic properties of polymers 3.1 thermodynamics and fluctuation 5.2 thermodynamics and fluctuation 5.2 thermodynamics and fluctuation 5.2 therendynamics of interfaces <		exam			40								
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the regulations of study none Recommended prerequisites mechanics, thermo dynamics, statistical physics Acquired skills and knowledge the students • learn basic terms, concepts and phenomena of biological phy • learn models of the (bio)polymer-theory, microfluidic, radiation nanobiotechnology, membranes and neuronal networks • adapt skills in the independent processing of problems and de literature. They will be able to translate a biological oberserva ical question. 1. radiation biophysics 1.1 natural radiation 1.2 radiation protection 1.4 energy transfer in biological systems 1.5 biophysical concepts and biological response to ionizing 2. microfluidics 2.1 Navier-Stokes equation 2.2 life at low Reynolds numbers 2.3 microfluidic phenomena 2.4 Lab-on-a-Chip systems 3. dynamic properties of polymers 3.1 the Rousse model 3.2 the Zimm model 3.3 reptation 3.4 viscoelastic networks 4 membranes 5.1 thermodynamics and fluctuation 5.2 thermodynamics of interfaces 5.3 phase transition – 2 state model 5.4 membrane elasticity 5. neuronal networks <td></td> <td>6</td> <td></td> <td></td> <td></td> <td></td> <td></td> <td></td>		6											
The regulations of study mechanics, thermo dynamics, statistical physics Recommended prerequisites mechanics, thermo dynamics, statistical physics Acquired skills and knowledge the students • learn basic terms, concepts and phenomena of biological phy • learn models of the (bio)polymer-theory, microfluidic, radiation nanobiotechnology, membranes and neuronal networks • adapt skills in the independent processing of problems and de literature. They will be able to translate a biological oberservatical question. 1. radiation biophysics 1.1 natural radiation 1.2 radiation protection 1.4 energy transfer in biological systems 1.5 biophysical concepts and biological response to ionizing 2. microfluidics 2.1 Navier-Stokes equation 2.2 life at low Reynolds numbers 2.3 microfluidic phenomena 2.4 Lab-on-a-Chip systems 3.4 viscoelastic networks 4 membranes 5.1 the Rousse model 3.2 the Zimm model 3.3 reparation 3.4 viscoelastic networks <td< td=""><td></td><td>none</td><td></td><td></td><td></td><td></td><td></td><td></td></td<>		none											
quisites Interfailles, thermo dynamics, statistical physics Acquired skills and knowledge the students • learn basic terms, concepts and phenomena of biological phy earn models of the (bio)polymer-theory, microfluidic, radiation nanobiotechnology, membranes and neuronal networks • adapt skills in the independent processing of problems and de literature. They will be able to translate a biological oberserva ical question. 1. radiation biophysics 1.1 natural radiation 1.2 radiation protection 1.4 energy transfer in biological systems 1.5 biophysical concepts and biological response to ionizing 2. microfluidics 2.1 Navier-Stokes equation 2.2 life at low Reynolds numbers 2.3 microfluidic phenomena 2.4 Lab-on-a-Chip systems 3. dynamic properties of polymers 3.1 the Rousse model 3.3 reptation 3.4 viscoelastic networks 4. membranes 5.1 thermodynamics of interfaces 5.3 phase transition – 2 state model 5.4 membrane elasticity 5. neuronal networks 7.1 ion channels 7.2 ion transport 7.3 electro physiology 7.4 dynamic neuronal processes	the regulations of study												
Acquired skills and knowledge the students learn basic terms, concepts and phenomena of biological phy learn models of the (bio)polymer-theory, microfluidic, radiation nanobiotechnology, membranes and neuronal networks adapt skills in the independent processing of problems and de literature. They will be able to translate a biological oberserva ical question. 1. radiation biophysics 1.1 natural radiation 1.2 radiation protection 1.4 energy transfer in biological systems 1.5 biophysical concepts and biological response to ionizing 2. microfluidics 2.1 Navier-Stokes equation 2.2 life at low Reynolds numbers 2.3 microfluidic phenomena 2.4 Lab-on-a-Chip systems 3. the Rousse model 3.2 the Zimm model 3.3 reptation 3.4 viscoelastic networks 4. membranes 5.1 thermodynamics and fluctuation 5.2 thermodynamics of interfaces 5.3 phase transition – 2 state model 5.4 membrane elasticity 5. meuronal networks 7.1 ion channels 7.2 ion transport 7.3 electro physiology 7.4 dynamic neuronal processes		mechanics there	no dvnamico	s statisti	cal nhvei	ics							
Acquired skills and knowledge learn models of the (bio)polymer-theory, microfluidic, radiation nanobiotechnology, membranes and neuronal networks adapt skills in the independent processing of problems and de literature. They will be able to translate a biological oberserva ical question. radiation biophysics radiation protection radiation protection radiation protection radiation protection radiation protection radiation protection radiation protection radiation protection sicrofluidics	quisites		no aynamio	, ວເຜເວເ	ca priyo								
Acquired skills and knowledge learn models of the (bio)polymer-theory, microfluidic, radiation nanobiotechnology, membranes and neuronal networks adapt skills in the independent processing of problems and de literature. They will be able to translate a biological oberserva ical question. radiation biophysics radiation biophysics radiation protection radiaton protection radiation protection		the students											
Acquired skills and knowledge • learn models of the (bio)polymer-theory, microfluidic, radiation nanobiotechnology, membranes and neuronal networks • adapt skills in the independent processing of problems and de literature. They will be able to translate a biological oberservatical question. • radiation biophysics 1.1 radiation biophysics 1.2 radiation in the low-dose regime 1.3 radiation protection 1.4 energy transfer in biological systems 1.5 biophysical concepts and biological response to ionizing 2. microfluidics 2.1 Navier-Stokes equation 2.2 life at low Reynolds numbers 2.3 microfluidic phenomena 2.4 Lab-on-a-Chip systems 3. dynamic properties of polymers 3.1 the Rousse model 3.2 the Zimm model 3.3 reptation 3.4 viscoelastic networks 4. membranes 5.1 thermodynamics and fluctuation 5.2 thermodynamics of interfaces 5.3 phase transition – 2 state model 5.4 membrane 7.1 ion channels 7.2 ion transport 7.3 electro physiology 7.4 dynamic neuronal processes		a laara baaia ta		to and n	hanama	no of his		•					
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knowledge • adapt skills in the independent processing of problems and de literature. They will be able to translate a biological oberserva ical question. 1. radiation biophysics 1.1 natural radiation 1.2 radiation in the low-dose regime 1.3 radiation protection 1.4 energy transfer in biological systems 1.5 biophysical concepts and biological response to ionizing 2. microfluidics 2.1 Navier-Stokes equation 2.1 kab-on-a-Chip systems 3. dynamic properties of polymers 3.1 the Rousse model 3.2 the Zimm model 3.2 the Zimm model 3.3 reptation 3.4 viscoelastic networks 4. membranes 5.1 thermodynamics and fluctuation 5.2 thermodynamics of interfaces 5.3 phase transition – 2 state model 5.4 membrane elasticity 5. neuronal networks 7.1 ion channels 7.2 ion transport 7.3 electro physiology 7.4 dynamic neuronal processes 7.4 dynamic neuronal processes	Acquired skills and							iopnysics,					
Content In radiation in the independent processing of provents and deliver and the independent processes 1. radiation biophysics 1. radiation in the low-dose regime 1.3 radiation protection 1.4 energy transfer in biological systems 2.1 Navier-Stokes equation 2.2 life at low Reynolds numbers 2.3 microfluidic phenomena 2.4 Lab-on-a-Chip systems 3. dynamic properties of polymers 3.1 the Rousse model 3.2 the Rousse m								with ourroat					
ical question. 1. radiation biophysics 1.1 natural radiation 1.2 radiation in the low-dose regime 1.3 radiation protection 1.4 energy transfer in biological systems 1.5 biophysical concepts and biological response to ionizing 2. microfluidics 2.1 Navier-Stokes equation 2.2 life at low Reynolds numbers 2.3 microfluidic phenomena 2.4 Lab-on-a-Chip systems 3. dynamic properties of polymers 3.1 the Rousse model 3.2 the Zimm model 3.3 reptation 3.4 viscoelastic networks 4. membranes 5.1 thermodynamics and fluctuation 5.2 thermodynamics of interfaces 5.3 phase transition – 2 state model 5.4 membrane elasticity 5. neuronal networks 7.1 ion channels 7.2 ion transport 7.3 electro physiology 7.4 dynamic neuronal processes													
Content 1. radiation biophysics 1.1 natural radiation 1.2 radiation in the low-dose regime 1.3 radiation protection 1.4 energy transfer in biological systems 1.5 biophysical concepts and biological response to ionizing 2. microfluidics 2.1 Navier-Stokes equation 2.2 life at low Reynolds numbers 2.3 microfluidic phenomena 2.4 Lab-on-a-Chip systems 3. dynamic properties of polymers 3.1 the Rousse model 3.2 the Zimm model 3.3 reptation 3.4 viscoelastic networks 4. membranes 5.1 thermodynamics and fluctuation 5.2 thermodynamics of interfaces 5.3 phase transition – 2 state model 5.4 membrane elasticity 5. neuronal networks 7.1 ion channels 7.2 ion transport 7.3 electro physiology 7.4 dynamic neuronal processes				le to tran	islate a t	biologica	i operservatio	n into a pnys-					
1.1 natural radiation 1.2 radiation in the low-dose regime 1.3 radiation protection 1.4 energy transfer in biological systems 1.5 biophysical concepts and biological response to ionizing 2. microfluidics 2.1 Navier-Stokes equation 2.2 life at low Reynolds numbers 2.3 microfluidic phenomena 2.4 Lab-on-a-Chip systems 3. dynamic properties of polymers 3.1 the Rousse model 3.2 the Zimm model 3.3 reptation 3.4 viscoelastic networks 4. membranes 5.1 thermodynamics and fluctuation 5.2 thermodynamics of interfaces 5.3 phase transition – 2 state model 5.4 membrane elasticity 5. neuronal networks 7.1 ion channels 7.2 ion transport 7.3 electro physiology 7.4 dynamic neuronal processes		ical question.											
	Content	 radiation biophysics radiation biophysics natural radiation radiation in the low-dose regime radiation protection radiation protection energy transfer in biological systems biophysical concepts and biological response to ionizing radiation microfluidics Navier-Stokes equation life at low Reynolds numbers microfluidic phenomena Lab-on-a-Chip systems dynamic properties of polymers the Rousse model the Rousse model reptation dviscoelastic networks membranes thermodynamics and fluctuation thermodynamics of interfaces phase transition – 2 state model membrane elasticity neuronal networks ion channels ion transport 											
Requirements for cre- dits 1 written examination, 90 min		1 written examina	ation, 90 mii	ו									

Media and methods	lecture: transparencies/chalkboard with additional media exercise: talks to current problems in biophysics
Literature	 PG. De Gennes, Scaling Concepts in Polymer Physics (Cornell University Press) L.D. Landau and E.M. Lifschitz, Vol. 5 and 7 (Harri Deutsch) P. Nelson, Biological Physics (W. H. Freeman) T. Heimburg, Thermal Biophysics of Membranes (Wiley-VCH) D. Boal, The Mechanics of the Cell (Cambridge University Press)
Further information	This lecture is part and requirement for the methodical course Methods in Bio- physics. Lecture alone will be awarded 6 CP, Method Course 8 CP

Module description	Solid State Spectroscopy with Synchrotron Radiation									
Signature	MaMawi-41									
Semester and recur-				, <u>Dama</u>		e,	,			
rence	2 nd Semeste	er / every	year							
Responsible for module	Prof. Dr. Ku									
Lecturer	Prof. Dr. Ku	ntscher								
Language	english									
Curriculum inclosures	Master Mate rials; Maste						dvanced Func	tional Mate-		
_		Type	, Daomoio	SWS		Group	size			
Lecture type and hours		Vorlesu	ing	3		8-10				
		Übunge		1		8-10				
			Presen	се	Self-s	tudy	Total			
			time		Sell-S	luuy	TOLAT			
Work load	Vorles	ung	45		45		90	_		
(hours)	Übung		15		45		60			
	Prüfun	g			30		30	_		
0 111 1 1							180			
Credit points	6									
Prerequisites acc. to	none									
the regulations of study										
Recommended prere- quisites	Basic know	Basic knowledge in solid state physics								
Acquired skills and knowledge	 know the have ac spectros and hav troscopy 	 The students know the basics of spectroscopy and important instrumentation and methods. have acquired the skills of formulating a mathematical-physical ansatz in spectroscopy and can apply these in the field of solid state spectroscopy, and have the competence to deal with current problems in solid state spectroscopy autonomously, and are able to judge proper measurement methods for application. 								
Content	 Spectral ter, inter Excitation Infrared Ellipsom Photoer X-ray ab Neutron 	 Electromagnetic radiation: description, generation, detection [5] Spectral analysis of electromagnetic radiation: monochromators, spektrometer, interferometer [2] Excitations in the solid state: Dielectric function [2] Infrared spectroscopy [3] Ellipsometry [2] Photoemission spectroscopy [2] X-ray absorption spectroscopy [1] Neutrons: Sources, detectors [2] Neutron scattering [2] 								
Requirements for cre- dits	Oral examir	nation, 30	min.							
Media and methods	Beamer pre	sentatior	1							
Literature	 H. Kuzmany, Solid State Spectroscopy (Springer) N. W. Ashcroft, N. D. Mermin, Solid State Physics (Holt, Rinehart and Winston) J. M. Hollas, Modern Spectroscopy 									
Further information	-									

Module description	Chemische	Chemische Physik I									
Signature				5, MaPh	v-24-06	, MaPhy-	41-02, BaMa	wi-64-04			
Semester and recur- rence	jedes Winte				5		·				
Responsible for module	Prof. Dr. Sc										
Lecturer	Prof. Dr. Sc	herer, Dr.	. Eickerlir	ng							
Language	Deutsch										
Curriculum inclosures	Master Mate Bachelor M				pflichtm	odul); Ma	ster AFM; Ma	ster Physik;			
		Lehrfor		SWS		Gruppe	ngröße				
Lecture type and hours		Vorlesu	ng	3		10-30					
		Übunge	en	1		10-30					
			Präsen	zzeit	Eigen	studium	Gesamt				
	Vorles	ung	45		45		90				
Work load	Übung		15		45		60				
(hours)	Klausu				30		30				
							180				
Credit points	6										
Prerequisites acc. to	keine										
the regulations of study	_ · ·		D 1					1			
Recommended prere- quisites	praktikum"	die Versu	che FP11	l (IR-Sp			ches Fortges FP17 (Rama				
4	Spektrosko		solvierer) .							
	Die Studier			_							
			lagen dei	r Extend	led Hüc	kel Metho	de und der D	ichtefunktio-			
	nal Theo										
Acquired skills and							ruppentheorie				
knowledge								ahmen der			
line meage	die aus Symmetrieüberlegungen gewonnenen Erkenntnisse im Rahmen der Schwingungs-, NMR- und UV/VIS-Spektroskopie anwenden,										
							hen, elektron				
				en von l	Jbergan	gsmetallk	omplexen zu	interpretie-			
		ren und vorherzusagen.									
	1. Grundla										
	- Die Extended Hückel Methode (EHM)										
	- Moderne quantenchemische Methoden der Chemischen Physik										
	 Anwendung: Beispielrechnungen und Interpretation einfacher elektronischer Strukturen 										
	2. Moleküle						-				
Content		mmetrieo		en una N	latrixoa	rstellunge	n				
Content		Inktgruppe		ziblo Do	rotollun	aon					
		duzible u			irsteilun	gen					
		arakterta			man_Qr	aktrocko	oie, NMR-Spe	aktroskonia			
	3. Die Elek							skuoskopie			
		gandfeldth									
		e physikal									
		blekülorbit									
							rer Magnetisr	mus			
Requirements for credits	Klausur, etv										
Media and methods	Tafelvortrag	und Rea	mer-Präs	entation	n						
						(Toubace)					
		old, Quan				(reubner)	1				
		hmidtke, (. ,						
		rris und N	1. D. Bert	olucci, S	Symmet	ry and Sp	ectroscopy (E	Dover Publi-			
	cations)										
Literature	• D. M. Bis	shop, Gro	up Theor	y and C	hemistr	y (Dover I	Publications)				
	• J. K. Bur	dett, Chei	mical Bor	nds: A D) ialog (V	Viley)					
						• •	niversity Pres	ss)			
		-	-		-		ure Methods				
		burg, PA)		ony with				Caussian			
				alichke	it im Ra	hmen der	Übungen se	elbständig			
Further information											
		einfache EH, HF und DFT Rechnungen und Analysen elektronischer Strukturen									

von Molekülen auf einem Computer-cluster durchzuführen. The lecture "Chemische Physik I" is one of the regular lectures of the physics
masters program and is therefore only offered in German language.

Module description	Chemische Physik II									
Signature	MaMawi-41	-07, MaA	FM-41-0	7, MaPł	y-24-06	, MaPhy	-41-02, BaMa	awi-64-04		
Semester and recur- rence	jedes Somr	nersemes	ster							
Responsible for module	Prof. Dr. Sc									
Lecturer	Prof. Dr. Sc	herer, Dr	. Eickerlii	ng						
Language	Deutsch									
Curriculum inclosures	Master Mate Bachelor M				lpflichtm	odul); Ma	aster AFM; M	laster Physik;		
	Dachelor M	Type	361136114	SWS		Group	size			
Lecture type and hours		Vorlesu	Ina	3		10-30	0/20			
Lecture type and nouis		Übungen 1 10-30								
		Presence								
			time		Self-s	tudy	Total			
Work load	Vorles	ung	45		45		90			
(hours)	Übung		15		45		60			
()	Klausu		-		30		30			
		-					180			
Credit points	6		1							
Prerequisites acc. to	lu a lua a									
the regulations of study	keine									
Recommended prere-	Es wird drin	gend em	pfohlen,	das Moo	dul Cher	nical Phy	sics I zuerst	zu absolvie-		
quisites	ren.	0	. ,			,				
Acquired skills and knowledge	 zur Interpretation elektronischer Strukturen in Molekülen und Festkörpern. besitzen somit die Fertigkeit u.a. die Quantum Theorie der Atome in Molekülen (QTAIM) und gängige Elektronenlokalisierungsfunktionen (z. B. ELF) zur Analyse von Ladungsdungs- und Spindichteverteilungen anzuwenden. sind kompetent selbstständig einfache quantenchemische Rechnungen unter Verwendung der Dichtefunktionaltheorie (DFT) durchzuführen und die elektronischen Strukturen funktioneller Moleküle und Materialien im Hinblick auf chemische und physikalische Eigenschaften zu interpretieren. 									
Content	 Die Quant Elektroner 3. Die Natur 4. Analyse 	der Topol entheorie hlokalisier r der che von Welle	ogie von der "Ato rungsfunł mischen enfunktior	Spin- u me in M ktionen Bindung nen mitt	nd Ladu lolekülei (ELF) ur g [5] els lokal	ngsdicht n" (QTAII nd –Indik isierter C	everteilunger M) atoren (ELI)			
Requirements for cre-	Klausur, etv	va 90 min	n							
dits Madia and matheda										
Media and methods	Tatelvortrag	g und Bea	imer-Prä	sentatio	n					
Literature	 Tafelvortrag und Beamer-Präsentation J. Reinhold, Quantentheorie der Moleküle (Teubner) HH. Schmidtke, Quantenchemie (VCH) J. K. Burdett, Chemical Bonds: A Dialog (Wiley) F. A. Kettle, Physical Inorganic Chemistry (Oxford University Press) R. F. W. Bader, Atoms in Molecules: A Quantum Theory (Oxford University Press) P. Popelier, Atoms in Molecules: An Introduction (Pearson Education Limited) F. Weinhold, C. R. Landis, Valency and Bonding: A Natural Bond Orbital Donor-Acceptor Perspective (Cambridge University Press) A. Frisch, Exploring Chemistry with Electronic Structure Methods (Gaussian 									
Further information	Die Student nungen und auf einem C	I Analyse Computer Physik I	en die Me n elektro cluster im I" is one e	nischer n Rahmo of the re	Struktur en der Ü egular le	en von M bungen ctures of	durchzuführe the physics	sche Rech- d Festkörpern en. The lecture masters pro-		

Module description	Ion-Solid I	otoractio	n					
Signature	MaMawi-41			8 MaPh	v-24-00)		
Semester and recur-				o, mai 1	y <u>∠</u> - ⊺ -0a	,		
rence	2 nd Semeste	er / every	year					
Responsible for module	PrivDoz. D)r Karl						
Lecturer	T 11VD02. L	n. Nan						
	English							
Language	English Maatar Mat					ula). Mar		atar Dhuaile
Curriculum inclosures	(Wahl)		enschafte		ve moa		ster FAME; Ma	Ister Physik
		Туре		SWS		Group	size	_
Lecture type and hours		Vorlesu	ing	3		10-15		_
		Übung	T	1	T	10-15		
			Preser	nce	Self-s	tudv	Total	
			time		00// 0	lady	10101	
Work load	Vorle	sung	45		45		90	
(hours)	Übun	g	15		45		60	
	Klaus	sur			30		30	
							180	
Credit points	6							
Prerequisites acc. to	-							
the regulations of study	keine							
Recommended prere-	0 "		DI ''					
quisites	Grundkennt	inisse aus	s Physik	I – IV, F	estkörpe	erpnysik,	Kernphysik	
Acquired skills and knowledge	 der Wechselwirkung von Teilchen und Festkörpern im Energiebereich von eV bis MeV, sind in der Lage, geeignete physikalische Modelle für spezifische technologi- sche und wissenschaftliche Anwendungen auszuwählen, und sind kompetent, Probleme aus dem Bereich der Wechselwirkung zwischen Ionen und Festkörpern weitgehend selbständig zu bearbeiten. 							
Content	 Folgende Themen bzw. Themenkreise werden behandelt: Introduction (areas of scientific and technological application, principles) [2] Fundamentals of atomic collision processes (scattering, cross-sections, energy loss models, potentials in binary collision models) [6] Ion-induced modification of solids (integrated circuit fabrication with emphasis on ion induced phenomena, ion implantation, radiation damage, ion milling and etching (RIE), sputtering, erosion, deposition) [8] Transport phenomena [2] Analysis with ion beams [4] 							
Requirements for cre- dits	1 written ex							
Media and methods	Iatelvortrag	g, ggf. mit	Folienur	nterstütz	ung, Be	amer-Pra	asentation	
Literature	 Tafelvortrag, ggf. mit Folienunterstützung, Beamer-Präsentation R. Smith, Atomic and ion collisions in solids and at surfaces (Cambridge University Press, 1997) E. Rimini, Ion implantation: Basics to device fabrication (Kluwer, 1995) W. Eckstein: Computer Simulation of Ion-Solid Interactions (Springer, 1991) H. Ryssel, I. Ruge: Ionenimplantation (Teubner, 1978) Y. H. Ohtsuki: Charged Beam Interaction with Solids (Taylor & Francis, 1983) J. F. Ziegler (Hrsg.): The Stopping and Range of Ions in Solids (Pergamon) R. Behrisch (Hrsg.): Sputtering by Particle Bombardment (Springer) M. Nastasi, J. K. Hirvonen, J. W. Mayer: Ion-Solid Interactions: Fundamentals and Applications (Cambridge University Press, 1996) http://www.SRIM.org 							
Further information	-	-						

Module description	Phys	sics of	Thin Films	5					
Signature	MaN	lawi-41	-09, MaAFI	M-41-0	9, MaPh	y-24-10	, BaMaw	/i-64-07	
Semester and recur-			emester / e						
rence				very z	year				
Responsible for module		. Dr. Bri							
Lecturer			I, Prof. Dr.	Mannh	art (SS 2	2011)			
Language	Engl								
Curriculum inclosures			module); E				ence	al Materials, N	Master Phys-
Lecture type and hours		Type SWS Group size							
			Vorlesun	Ÿ	4	1	10-15	-	
Worklood				Prese time	ence	Self-s	tudy	Total	
Work load (hours)		Vorlesu	ung	60		60		120	
(nours)		Klausu	r			60		60	
								180	
Credit points	6								
Prerequisites acc. to the regulations of study	none	Э							
Recommended prereq- uisites	none	none							
Acquired skills and knowledge	 The students know methods of thin film technology and material properties and applications of thin films, have acquired skills of grouping the various technologies for producing thin layers with respect to their properties and applications, and have the competence to deal with current problems in the field of thin film technology largely autonomous. 							ducing thin	
Content	• T • A	Thin film Analysis	owth [2] technolog of thin filn es and app	ns [8]	s of thin	films [1	0]		
Requirements for cred- its	1 wr	itten exa	amination,	90 min					
Media and methods	Blac	kboard	and/or bea	mer pre	esentatio	on			
Literature	 H. Frey, G. Kienel, Dünnschichttechnologie (VDI Verlag, 1987) H. Lüth, Solid Surfaces, Interfaces and Thin Films (Springer Verlag, 2001) A. Wagendristel, Y. Wang, An Introduction to Physics and Technology of Thin Films (World Scientific Publishing, 1994) M. Ohring, The Materials Science of Thin Films (Academic Press, 1992) 								
Further information	-								

Module description	Organic Semiconductors									
Signature	MaMawi-41-10, MaAFM		v-24-11							
Semester and recur-	2 nd or 3 rd Semester / ev		,							
rence	2 or 3 Semester / ev	/ery z year								
Responsible for module	Prof. Dr. Brütting									
Lecturer										
Language	English									
Curriculum inclosures	Master Materials Scien ics (elective module)		/anced I			aster Phys-				
Lecture type and hours	Type	SWS		Group s	ize					
	Lecture	4	1	10-15						
		Presence time	Self-s	tudy	Total					
Work load	Lecture	60	60		120					
(hours)	Written exam		60		60					
					180					
Credit points	6									
Prerequisites acc. to the regulations of study	none									
Recommended prere-	It is strongly recommen	nded to comple	te the m	odule soli	d-state physic	cs first. In				
quisites	addition, knowledge of	molecular phy	sics is d	esired.						
Acquired skills and knowledge	 have acquired skills for the classification of the materials taking into account their specific features in the functioning of components, and have the competence to comprehend and attend to current problems in the field of organic electronics. 									
Content	 Structural pro Electronic strutral Optical and e Devices and Applica Organic meta Light-emitting Field-effect training 	 Introduction [15] Materials and preparation Structural properties Structural properties Electronic structure Optical and electrical properties Devices and Applications [15] Organic metals Light-emitting diodes Field-effect transistors Solar cells and laser 								
Requirements for cre- dits	1 written examination, s	90 min								
Media and methods	Blackboard and/or bear	mer presentati	on							
Literature	 M. Schwoerer, H. C. Wolf, Organische Molekulare Festkörper (Wiley-VCH, 2005) M. Schwoerer, H. C. Wolf, Organic Molecular Solids (Wiley-VCH, 2007) M. Pope, C. E. Swenberg, Electronic Processes in Organic Crystals and Polymers (Oxford University Press 1999) W. Brütting, Physics of Organic Semiconductors (lecture script) 									
Further information	-									

Module description	Magnetism								
Signature	MaMawi-41-11, Ma	aAFM-41-1	1, MaPh	y-24-12	, BaMaw	ʻi-64-10			
Semester and recur-	ab dem 1. Semest	ar / annual							
rence									
Responsible for module	PrivDoz. Dr. Krug	von Nidda	a						
Lecturer	PrivDoz. Dr. Krug								
Language	english or german,								
Curriculum inclosures	Master Materials S ics (elective modul					al Materials; N	laster Phys-		
_	Type		SWS		Group	size			
Lecture type and hours	Lectu		3		5-10		-		
	Exerc	Exercices 1 5-10							
		Prese	nce	Solf	tudu	Total			
		time		Self-s	tudy	Total			
Work load	Lecture	45		30		75			
(hours)	Exercices	15		60		75			
	Exam			30		30			
						180			
Credit points	6								
Prerequisites acc. to	none								
the regulations of study									
Recommended prere-	Basics of solid-stat	e physics	and quar	ntum me	chanics				
quisites			ana qua						
Acquired skills and knowledge	 most important methods and concepts for their description, like mean-field theory, exchange interactions and micro magnetic models have the ability to classify different magnetic phenomena and to apply the corresponding models for their interpretation have the competence independently to treat fundamental and typical topics and problems of magnetism. 								
Content	 History, basics [1] Magnetic moments, classical and quantum phenomenology [4] Exchange interaction and mean-field theory [3] Magnetic anisotropy and magnetoelastic effects [3] Thermodynamics of magnetic systems and applications [2] Magnetic domains und domain walls [2] Magnetization processes und micro magnetic treatment [2] AC susceptibility and ESR [2] Spintransport / spintronics [2] Recent problems of magnetism [2] 								
Requirements for cre- dits	Oral examination,	30 min.							
Media and methods	Black board, overh	ead, and b	peamer p	resenta	tion				
Literature	 Black board, overhead, and beamer presentation D. H. Martin, Magnetism in Solids (London Iliffe Books Ltd.) J. B. Goodenough, Magnetism and the Chemical Bond (Wiley) P. A. Cox, Transition Metal Oxides (Oxford University Press) C. Kittel, Solid State Phyics (Wiley) D. C. Mattis, The Theory of Magnetism (Wiley) G. L. Squires, Thermal Neutron Scattering (Dover Publications Inc.) 								
Further information	-								

Module description	Low Temp	erature P	hysics							
Signature	MaMawi-41			2. MaPh	v-24-14	1				
Semester and recur-					,					
rence	2 nd or 3 rd S	emester /	every 2	year						
Responsible for module	Prof. Dr. M	annhart								
Lecturer										
Language	English									
Curriculum inclosures				ster Adv	vanced	Function	al Materials;	Master Phys-		
Curricularit inclosures	ics (elective					1				
		Type SWS Group size								
Lecture type and hours		Lecture		3		8-10				
		Exercices 1 8-10								
			Preser	ce	Self-s	studv	Total			
			time							
Work load	Lectur		45		45		90			
(hours)	Exerci	ces	15		45		60			
	Exam				30		30			
							180			
Credit points	6									
Prerequisites acc. to the regulations of study	none									
Recommended prere- quisites	Physik IV –	Solid-sta	te physic	s						
Acquired skills and knowledge	 know the basic properties of matter at low temperatures and the corresponding experimental techniques, have acquired the theoretical knowledge to perform low-temperature measurements, and know how to experimentally investigate current problems in low-temperature physics. 									
Content	 Introduction [1] Quantum Fluids [6] Helium 4 Helium 3 Quantum Solids [1] Bose-Einstein Condensate [2] Material Properties at Low Temperatures [6] Heat capacity Thermal conductivity Electric conductivity Low temperature techniques [5] Cooling Temperature measurement Design of cryogenic equipment Overview on state of current research [1] 									
Requirements for cre- dits	Oral exami									
Media and methods	Lecture at l	olackboar	d, using t	ranspar	encies	and comp	outer projecti	ion		
Literature		s, S. Hunk II, Matter					inger) es (Springer))		
Further information	-									

Module description	Spir	ntronics	3								
Signature		MaMawi-41-13, MaAFM-41-13									
Semester and recur- rence	2 nd c	or 3 rd Se	emester / e	very 2 nd	' year						
Responsible for module		. Dr. Bri									
Docent			l, Prof. Dr.	Mannh	art (WS	2011/12	2)				
Language		English									
Curriculum inclosures	Mas	Master Materials Science; Master Advanced Functional Materials									
Lecture type and hours			<i>Type</i> Vorlesun	g	SWS 4		Group 15-25	size	_		
				Prese time	ence	Self-s	tudy	Total			
Work load (hours)		Vorlesu	ung	60		60		120			
(nours)		Klausu	r			60		60			
								180			
Credit points	6										
Prerequisites acc. to the regulations of study	none	none									
Recommended prereq- uisites	none	none									
Acquired skills and knowledge	 k e f a 	effects, and the related device structureshave acquired skills in identifying materials with respect to their applicability for spintronic devices									
Content	 Introduction into magnetism [4] Basic spintronic effects and devices [4] Novel materials for spintronic applications [4] Spin-sensitive experimental methods [4] Semiconductor based spintronics [4] 										
Requirements for cred- its			amination,								
Media and methods	Blac	kboard	and/or bea	amer pre	esentatio	on					
Literature	• 5	S. Band	yopadhyay	, М. Ca	hay: Inti	roductio	n to Spir	ntronics (CRC	2008) Press, 2008)		
Further information	-										

Module description	Materials Synthesis								
Signature	MaMawi-41	-14, MaA	FM-41-1	4, MaPh	iy41-05,	MaPhy-	42-07, BaMav	vi-64-09	
Semester and recur- rence	winter term	/ each ye	ar						
Responsible for module	Prof. Dr. Sc	herer							
Lecturer									
Language	English								
Curriculum enclosures	Master Mate ics; Bachelo				vanced I	-	al Materials; N	laster Phys-	
Lecture type and hours	Lecture type Lecture typ and hours hours							_	
Work load (hours)	Work lo (hours)				Work (hours			Work load (hours)	
Credit points	6						·	·	
Prerequisites acc. to	none								
the regulations of study Recommended prere- quisites	none								
Acquired skills and knowledge	 The students know the basic approaches to synthesize functional materials and obey a fundamental knowledge of the respective microscopic reaction mechanisms involved. obey the capability to classify materials with respect to their individual synthetic routes. obey the competence to adopt established synthesis approaches for the design of new materials 								
Content	 Solid-s Decorr Interca Chemi Chemi Chemi Chemi Aeroso materia Solvo-1 Sol-Ge excurs excurs 	 Introduction: examples of materials syntheses Solid-solid reactions (ceramic methods) Decomposition – and dehydratisation reactions Intercalation reactions Chemical transport Chemical vapor deposition (CVD) Aerosol processes materials from solution and melts 							
Requirements for cre- dits	1 written ex	aminatior	n, 90 min						
Media and methods	Blackboard	presenta	tion, eve	ntually w	vith bear	mer proje	ection techniqu	ues	
Literature	 Blackboard presentation, eventually with beamer projection techniques U. Schubert, N. Hüsing, Synthesis of Inorganic Materials (Wiley-VCH) D. W. Bruce, D. O'Hare, Inorganic Materials (John Wiley & Sons) JP. Jolivet, Metal Oxide Chemistry and Synthesis – From Solution to Solid State (John Wiley & Sons) W. Jones, C.N.R. Rao, Supramolecular Organization and Materials Design (Cambridge University Press) L.V. Interrante, M.J. Hampden Smith, Chemistry of Advanced Materials – An Overview (Wiley) G.A. Ozin, A.C. Arsenault, Nanochemistry – A Chemical Approach to Na- nomaterials, (RSC Publishing) 							y-VCH) ns) lution to Solid erials Design Materials –	
Further information	7. A.R.	••05t, Da			normoti		Viley & Sons)		
	-								

Module description	Oxidation	and Co	rrosion								
Signature	MaMawi-41-15, MaAFM-41-15										
Semester and recurren-	3 rd semest	or / wint	or torm								
се	5 Serries										
Responsible for module	Prof. Dr. H	laider									
Lecturer											
Language	English										
Curriculum inclosures	Master of	Science	Materials			r Advan	ced Functiona	al Materials			
		Туре		SWS		Group	o size				
Lecture type and hours		Vorlesu		4		20-40					
Lecture type and nouis		Practic	al Exer-	1		3					
		cises		-		0	T				
			Preser	ice	Self-s	tudv	Total				
			time			iteren y		_			
Work load (hours)	Vorles		60		60		120	_			
	Practic		8		40		48				
							168				
Credit points	6										
Prerequisites acc. to the	none										
regulations of study						_					
Recommended prerequi-		ntnisse de	er Materia	alwisser	nschaftei	n, Gruno	kenntnisse de	er physik.			
sites	Chemie	,									
	Die Studie				~ "						
Acquired skills and	Iernen die elementaren Grundlagen, Vorgänge und Erscheinungs- formen von Korrosionenrozoogen konnen										
	formen von Korrosionsprozessen kennen										
knowledge	 erarbeiten sich speziellere praktische Kenntnisse f ür ein Beispiel ei- ner Korrosionsform 										
		ner Korr	osionsioi	m							
Content	P C Ir S F E G Water and Corrosion Corrosion Specific co A F corrosion P R C C C C C C C C C C C C C C C C C C	thermod equilibria mistry kinetics erature of corrosion hallow pi itting cor revice con atercrysta tress cor atigue co rosion co seawate monitorin propertie prosion p il and Ga utomobil ood indu protection assive la eaction l oatings (athodic,	axidation it corrosion prosion alline corr prosion cra prosion corrosi corrosion corrosion corrosion corrosi corrosion corrosi	osion acking on ific mat in certa y / ffusion norgan	ain branc layers ic)						
	Inhibitors Prakt. Übung, Vortrag und Ausarbeitung 30-45 min										
Requirements for credits		ing, Vorti	rag und A	usarbe	itung 30	0-45 mir	1				
Requirements for credits Media and methods				usarbe	itung 30	0-45 mir)				

Literature	6. Schütze: Corrosion and Environmental Degradation
Further information	

Module description	Sem	inar or	Glass P	hvsics							
Signature	Seminar on Glass Physics MaMawi-41-16, MaAFM-41-16, MaPhy-31-09										
Semester and recur-			er / each s			•					
rence	2 5	emeste	er / each s	summer s	semeste	-					
Responsible for module		-	kenheime								
Lecturer	PD D	r. Luni	kenheime	r (SS 20'	11)						
Language	Engli	sh									
Curriculum inclosures	Mast ics	er Mate	erials Scie	ence; Ma	ster Adv	anced	Functiona	al Materials;	Master Phys-		
	103		Туре		SWS		Group	size			
Lecture type and hours		Seminar 2 10-12									
Work load		Presence time Self-study Total									
(hours)		Semi	nar	time 30		90		120			
Credit points	4	Oemi		50		30		120			
Prerequisites acc. to	none										
the regulations of study	none										
Recommended prere- quisites	Basio	c know	edge of s	olid-state	e physics	6					
Acquired skills and knowledge	sit m ce Th ria pr pr m • Th im	 The students know the phenomenology of the glass state and the glass transition, the material properties of glasses, their technical applications and the most important models of glassy matter. They have acquired knowledge concerning the preparation of scientific presentations. They are able to independently acquaint themselves with a physical or material-science topic using various sources of information. They are capable of preparing a graphically attractive scientific talk using modern, computer-based presentation techniques. They are able to present a talk in a clear and informative way, adhering to a fixed time limit. The students have the competence to distinguish between important and less important contents when preparing a scientific talk and to edit and restructure the chosen contents in order to provide a didactically sound presentation. 									
Content	- Te - Po - Me - Re - Mo - Ag - No - Ioi	echnica olymers etallic g elaxatic odels o ging ph on-strue nic con	g topics a glasses on phenor f the glas enomena ctural glas ductivity s in glasse	nena s transitio in glasso sses	on						
Requirements for cre- dits	Talk	with dis	scussion,	about 60) min						
Media and methods	Bear	ner pre	sentation								
Literature	 H. Scholze, Glas (Vieweg) S.R. Elliott, Physics of Amorphous Materials (Longman) R. Zallen, The Physics of Amorphous Solids (Wiley) J. Zarzycki (ed.), Material Science and Technology, Vol. 9: Glasses and Amorphous Materials (VCH) J. Zarzycki, Glasses and the Vitreous State (Cambridge University Press) 										
Further information	-										

Modul description	Advanced Solid State Materials										
Signature	MaMawi-4	MaMawi-41-17, MaAFM-41-17, MaPhy-41-07									
Semester and recur-	2 nd semes										
rence			Summer	enn							
Responsible for module	Prof. Dr. H										
Lecturer	Prof. Dr. H	löppe									
Language	English	tariala Ca	ianaa (ala			Acoton A	du ana a di Tuma				
Curriculum inclosures	rials (elec						dvanced Func	tional Mate-			
		type	size								
Lecture type and hours		lecture	s	SWS	3	0.00.0	24	-			
, , , , , , , , , , , , , , , , , , ,		tutorial			1		24				
			Preser	nce	Self-s	tudy	Total				
			time		0011-3	luuy					
Work load	lectu			5		40	85	_			
(hours)	tutori	al	1	5	-	30	45	-			
	home	work				50	50				
							180	-			
Credit points	6		1		1						
Prerequisites acc. to											
the regulations of study	none	none									
Recommended prere- quisites	Contents	Contents of modules Chemistry I and Solid State Chemistry (Bachelor)									
Acquired skills and knowledge	 are aw function acquire composition gain control 	 The students are aware of correlations between composition, structures and properties of functional materials acquire skills to predict the properties of chemical compounds, based on their composition and structures gain competence to evaluate the potential of functional materials for future technological developments will know how to measure the properties of these materials. 									
Content	 luminescent materials [5] pigments [3] ion conductors [3] magnetic/data storage materials [3] thermoelectric materials [2] catalysts [4] hard materials [2] 										
Requirements for cre- dits	1 written e	examinatio	n, 90 min								
Media and methods	blackboar	d, beamer	presenta	tion occa	asionally	y					
Literature	 L. Sma 	st, Solid S art, E. Moc s Solid Sta	ore, Solid	State Ch	nemistry	/					
Further information	-										

Module description	Porous Materials										
Signature	MaMawi-41-18, MaPhy-41-08, MaPhy-42-08, MaAFM-41-18										
Semester and recur- rence	2 nd semest	er (each sumr	ner term)								
Responsible for module	Prof. Dr. V										
Lecturer	Prof. Dr. V	olkmer									
Language	English										
Curriculum inclosures		Master Materials Science (elective module); Master Advanced Functional Materials (elective module); Master Physics with minor subject Chemistry (elective									
	module)										
	Туре			SWS	Group size						
Lecture type and hours		lectures		3	20-30						
		tutorial		1	20-30						
			Presence time	Self-study	Total						
Work load		lectures	45	30	75						
(hours)		tutorial	15	60	75	1					
(10013)		homework		30	30	1					
			1		180	1					
Cradit paints	6				100						
Credit points	6										
Prerequisites acc. to	none										
the regulations of study Recommended prere-	Dortioinatio	n in the Cours	o Motoriolo (Chemistry: MaP	by 11 04 MoD	by 12.06					
quisites		3-01, MaAFM-		Shernistry. Mar	ny-41-04, Mar	11y-42-00,					
Acquired skills and knowledge	Broade special	emphasis laid	lities to chara I upon sorptic	acterize porous on and thermal chnical applicati	analysis						
Content	1. O 2. Si 3. Si 4. Si 5. Ai 6. Ti 7. C	 Structural families of porous frameworks [2] Structure Determination and Computer Modelling [3] Synthesis strategies [2] Adsorption and diffusion [3] Thermal analysis methods [3] Catalytic properties [3] 									
Requirements for cre- dits		kamination, 90									
Media and methods	Beamer pr	esentation, bla	ckboard (oco	casionally)							
Literature	(RSC Mat	/right, Micropo erials Monogr selected revie	aphs, 2008)	vork Solids al articles cited	on the slides						
Further information		e ("Solid State		students can ta MaMawi-24-09,							

Module description	Superconductivity									
Signature	MaMawi-41-19, MaAFM-41-19, MaPhy-24-18									
Semester and recur-		2 nd or 3 rd Semester / every 2nd year								
rence	2 ^{na} c	or 3 ^{ra} Se	emester /	every 2n	d year					
Responsible for module	Priv	- Doz	Dr. R. Tid	ecks						
Lecturer			Dr. R. Tid							
Language	Engl			00110						
			erials Sci	ence (ele	ctive mo	odule)	Master A	FM (elective r	nodule), Mas-	
Curriculum inclosures			(elective			Jaaloj, I				
			Type		SWS		Group	size		
Lecture type and hours			Lecture		4		40-50			
			Exercis		none		-			
				Presen						
				time		Self-s	study	Total		
Work load		Lectu	ire	60		75		135		
(hours)		Exer		-		-		-		
(Exan				45		45	_	
								180		
Credit points	6	I		1		1				
Prerequisites acc. to	-									
the regulations of study	None	e								
Recommended prere-	Dhu		0	4	- T L		h			
quisites	Phys	sik IV –	Solid-sta	te physic	s, Theor	etical p	nysics I-	111		
Acquired skills and knowledge	 By a presentation of experimental results they will learn the fundamental properties of the superconducting state. Special attention will be drawn to the basic concepts of the main phenomological and microscopic theories of the superconducting state, to explain the experimental observations. The students are informed about the most important technical application superconductivity. For self-studies a comprehensive list of further reading will be supplied. 							explain the		
Content	1. H 2. F 3. C 4. M 5. F 6. J 7. H	 Introductory Remarks and Literature[1] History and Main Properties of the Superconducting State, an Overview [1] Phenomenological Thermodynamics and Electrodynamics of the SC [4] Ginzburg-Landau Theory [4] Microscopic Theories[4] Fundamental Experiments on the Nature of the Superconducting State [3] Josephson-Effects [4] High Temperature Superconductors [5] Application of Superconductivity [4] 								
Requirements for cre- dits			nation, 20							
Media and methods	Hane	dwritter	n lecture a	at the ove	rhead p	rojecto	r, occasio	onal use of tra	nsparencies	
Literature	 W. Buckel, Supraleitung, 5. Auflage (VCH, Weinheim, 1994) W. Buckel und R. Kleiner, Superconductivity, 2nd edition (WILEY-VCH, Berlin, 2004) M. Tinkham, Introduction to Superconductivity, 2nd edition (McGraw-Hill, Inc., New York, 1996, Reprint by Dover Publications Inc. Miniola , 2004) A list of further literature will be given in the lecture. 									
Further information	-									

Modul description	Sustainable Resource Management									
Signature		MaMawi-41-20								
Semester and recurrence	2 nd	and 4th	¹ Semest	er / every year in	summer	term				
Responsible for module	Pro	of. Dr. F	Rathgebe	r / Prof. Dr. Relle	r					
Lecturers	Dr.	Meissr	ner / Phili	pp Mette / Prof. [. Thorenz		eber /				
Language	Ge	rman								
Curriculum inclosures	Ma	ster Ma	aterials S	cience (elective r	nodule)					
			Туре			SWS		Group size		
Lecture type and hours			lecture			2		30		
		1	exercis		1	2		30		
				Presence time	Self-st	udy	Total			
Work load		lectur	е	20	20		40			
(hours)		exerc	ise	20	80		100			
		writte men	n exa-		40		40			
							180			
Credit points	6									
Prerequisites acc.to the	No	ne								
regulations of study										
Recommended prerequi- sites	No	None								
Acquired skills and know- ledge	vancy of different resources like energy sources and metals. Furthermore students know risk management methods, which are used to identify, r and manage resource price risks. For this purpose, resource scarcity in risk measures and instruments for risk protection are being presented, enable the students to make economically well-grounded decisions in of with resources. Moreover, the students know how resource-based stra with the help of environmental management contribute to environmenta management. All topics are being illustrated with examples (from pract projects).							entify, measure arcity indicators, ented, which ons in dealing ed strategies nmental risk		
Content	 Introduction (global resource consumption) Overview of resource types Definition of mineral resources Introduction to resource management Identification of resource price risks Measurement of resource price risks Management of resource price risks Introduction in basics of environmental management Corporate environmental management Economical closed-loop systems 									
Requirements for credits				60 min, and prac						
Media and methods	Slie			with the help of of						
Literature	 Holger Rogall: Nachhaltige Ökonomie, Metropolis, Marburg, 2009. Hans-Dieter Haas, Dieter Matthew Schlesinger: Umweltökonomie und Ressourcenmanagement, Wissenschaftliche Buchgesellschaft, Darmstadt, 2007. Colin W. Clark: Mathematical Bioeconomics, Wiley, New York, 1976. Werner Gocht: Handbuch der Metallmärkte, 2. Aufl., Springer, New York / Tokyo, 1985. 							nomie und Res- Darmstadt, rk, 1976.		
Further information										

Modul description	Practical L	Practical Laboratory Project									
Signature	MaMawi-42	MaMawi-42-01, MaAFM-42-01									
Semester and recur-	3 rd or 4 th se	montor / on	oh oomo	otor							
rence	5 014 Se	mester / ea	ch seme	ester							
Responsible for module	Chairman o	f Examinati	on Boar	ď							
Lecturer	All Lecturer	All Lecturers and Professors of the Institute of Physics									
language		English / German									
Curriculum inclosures	Master Mat	Aster Materials Science; Master Advanced Functional Materials									
		type		SWS	Group size						
Lecture type and hours		lectures		N/A	N/A						
		tutorial		N/A	N/A						
		Practical course		N/A	N/A						
			Prese	ence time	Self-study	Total					
	lecture	es									
Work load	tutoria	1									
(hours)	Practical course		180			180					
	exami	nation									
						180					
Credit points	6										
Prerequisites acc. to											
the regulations of study											
Recommended prere-					Chemistry and M	laterials Scien	ce, both				
quisites	experiment	ally and the	eoretical	ly							
Acquired skills and knowledge	 know the the exist experie prepare 	 The students know the basic terms, skills and concepts to pursuit a real research project in the existing laboratories within the research groups, 									
Content		tal or theore Has to be o			ratory / research months.	n group in the I	nstitute				
Requirements for cre- dits	1 written re	port, editing	g time 2	weeks							
Media and methods	Face to fac	e tutoring									
Literature		various									
	• various										

5. Final Thesis and Colloquium

(1) The finals are part of the Master's examination and are ment to show that the candidate is in a position to solve a problem from the program independently according to scientific methods. The finals consist of the the written thesis and a colloquium in the form of an oral examination after submitting the thesis. For the thesis, 26 credit points are awarded and for the final colloquium 4 points.

(2) The processing time for the thesis between reception of the topic and submission of the thesis shall not exceed 6 months. The topic can be returned only once and only for good reasons within a period of four weeks after the issue of the topic. Consent of the Chairperson of the Examination Committee is required. If the thesis work needs to be redone, a change of the topic is not admitted.

(3) At the request of the candidate, and in exceptional cases, the processing time may be extended by a maximum of eight weeks. Again, the consent of the committee is required. Periods of medical disability (Doctor's testimony), or such for which the candidate cannot be held responsible, should be not counted towards the processing time. Here, too, the decision is with the examination board. Master thesis not being submitted in time will be assessed with "not sufficient".

(4) Working on the Masters thesis can only be started after the successful acquisition of at least 60 credit points from the module area 1 thru 5.

(5) The master's thesis should be written in English. Exceptions can only be given after consultation and decision of the examination board.

(6) The final colloquium is usually held during a period of four to six weeks after submitting the thesis. Subjects of the colloquium are the basic content of the courses in the Master program "Advanced Functional Materials well as the written thesis. The duration of the colloquium should not be less than 45 minutes and not exceeding 75 minutes. The colloquium starts with a presentation of approximately 15 minutes duration on the contents of the final work. A colloquium graded "insufficient" can be repeated within six months.

(7) A final Masters thesis graded with an "insufficient" may be repeated once. In this case, the topic has to be modified with respect to the original one.